TAS5825M 4.5 V to 26.4 V, 38-W Stereo, Inductor-Less, Digital Input, Closed-Loop Class-D Audio Amplifier with 96-kHz/192-kHz Extended Audio Processing

ADVANCE INFORMATION

1 Features

- Flexible Audio I/O:
  - Supports 32, 44.1, 48, 88.2, 96, 192 kHz Sample Rates
  - I^2S, LJ, RJ, TDM
  - SDOUT for Audio Monitoring, Sub-Channel or Echo Cancellation
  - Support 3-Wire Digital Audio Interface (No MCLK Required)
- Efficient Class-D Operation
  - Greater than 90% Power Efficiency, 90 mΩ R_{DS}on
- Support Multiple Output Configurations
  - 2 × 38W in 2.0 Mode (6-Ω, 24V,THD+N=1%)
  - 2 × 30W in 2.0 Mode (8-Ω, 24V,THD+N=1%)
- Excellent Audio Performance:
  - THD+N ≤ 0.04% at 1 W, 1 kHz, PVDD = 12 V
  - SNR ≥ 107 dB (A-weighted), ICN ≤ 45μVRMS
- Flexible Processing Features
  - 3-Band Advanced DRC+AGL
  - 2×15 BQs, Dynamic EQ
  - Sound Field Spatializer (SFS)
  - 96-kHz/192-kHz Processor Sampling
  - Smart Amplifier Algorithm for Bass Enhancement and Speaker Thermal/Excursion Protection
- Flexible Power Supply Configurations
  - PVDD: 4.5 V to 26.4 V
  - DVDD and I/O: 1.8 V or 3.3 V
- Excellent Integrated self-protection:
  - Over-Current Error (OCE)
  - Cycle-By-Cycle Current Limit
  - Over-Temperature Warning (OTW)
  - Over-Temperature Error (OTE)
  - Under/Over-Voltage Lock-out (UVLO/OVLO)
- Easy System Integration
  - I^2C Software Control
  - Reduced Solution Size
    - Small 5 x 5 mm Package
    - Less Passives Required Compare to Open Loop Devices
    - No Bulky Electrolytic Capacitors or Large Inductors Required for most Applications

2 Applications

- DTV, HDTV, UHD and Multi-Purpose Monitors
- Sounds Bars, PC Audio
- Wireless/Bluetooth Speakers
- Smart/Voice Control Speakers

3 Description

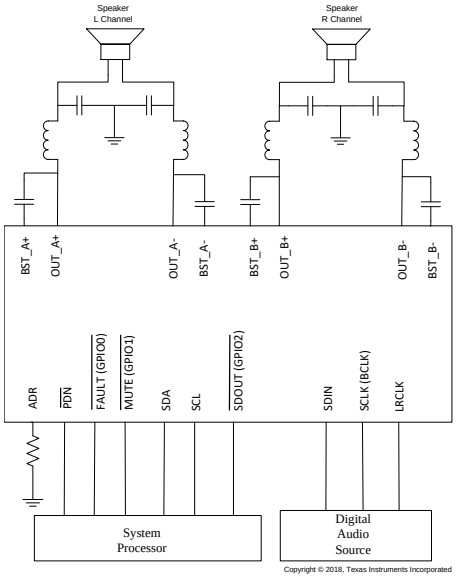
The TAS5825M is a high-performance, stereo closed-loop Class-D with integrated auido processor with up to 192-kHz architecture.

The powerful DSP audio processing core support several advanced audio process flows. Even with 192-kHz architecture, TAS5825M provide a rich processing, such as 2×12 BQs, volume control, audio mixer, 2 Band DRC and a Full Band AGL. With 48-kHz or 96-kHz architecture, an integrated SRC (Sample rate convertor) detects the input sample rate change and auto convert to the target sample rate which DSP is running to avoid any audio artifacts, these process flows support richer processing, such as 2×15 BQs, 3-Band DRC, Full-band AGL (Automatic Gain Limiter), Smart Amplifier Algorithm (Speaker Thermal/Excursion Protection), Bass enhancement, Spatializer, THD manager and so on.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TAS5825M	VQFN (32) RHB	5.00 mm × 5.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

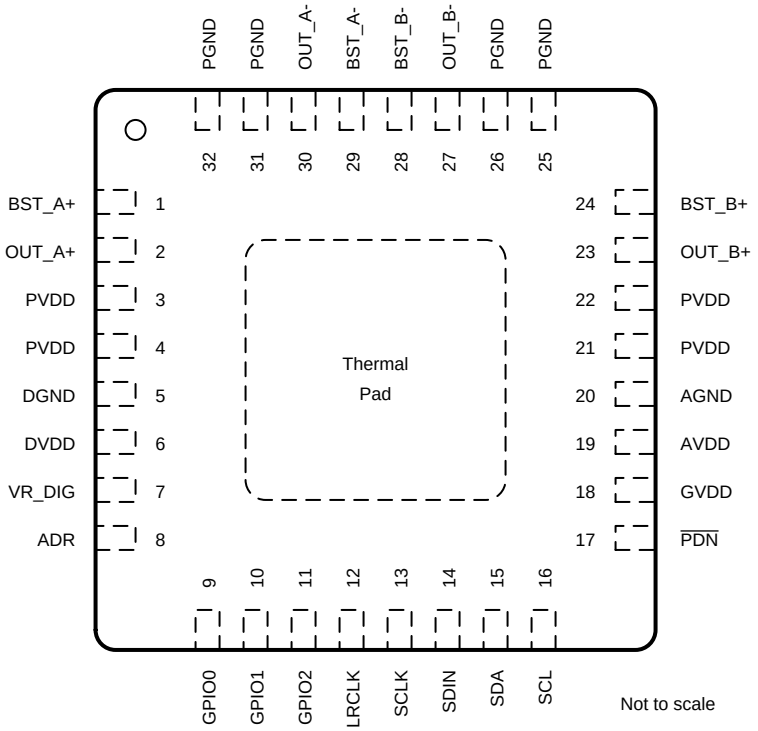
DATE	REVISION	NOTES
January 2018	*	Initial release.

5 Device Comparison Table

DEVICE NAME	DSP Audio Process Flows
TAS5825MRHB	Flexible Audio Process Flows

6 Pin Configuration and Functions

RHB Package
32-Pin VQFN



Pin Functions

PIN		TYPE[1]	DESCRIPTION
NAME	NO.		
DGND	5	P	Digital ground
DVDD	6	P	3.3-V or 1.8-V digital power supply
VR_DIG	7	P	Internally regulated 1.5-V digital supply voltage. This pin must not be used to drive external devices
ADR	8	AI	A table of resistor value (Pull up/down to DVDD/GND) will decide device I2C address. See Table 61.
GPIO0	9	DI/O	General-purpose input/output, function of this pin can be programmed by register (Register Address 0x60h and 0x61h)
GPIO1	10	DI/O	General-purpose input/output, function of this pin can be programmed by register (Register Address 0x60h and 0x62h)
GPIO2	11	DI/O	General-purpose input/output, function of this pin can be programmed by register (Register Address 0x60h and 0x63h)
LRCLK	12	DI	Word select clock for the digital signal that is active on the serial port's input data line. In I^2S, LJ and RJ, this corresponds to the left channel and right channel boundary. In TDM mode, this corresponds to the frame sync boundary.
SCLK[2]	13	DI	Bit clock for the digital signal that is active on the input data line of the serial data port. Sometimes, this pin also be written as "bit clock (BCLK)"
SDIN	14	DI	Data line to the serial data port

(1) AI = Analog input, AO = Analog output, DI = Digital Input, DO = Digital Output, DI/O = Digital Bi-directional (input and output), P = Power, G = Ground (0 V)
(2) Typically written "bit clock (BCLK)" in some audio codecs.

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Pin Functions (continued)

PIN		TYPE(1)	DESCRIPTION
NAME	NO.		
SDA	15	DI/O	I2C serial control data interface input/output
SCL	16	DI	I2C serial control clock input
$\overline{\text{PDN}}$	17	DI	Power down, active-low. $\overline{\text{PDN}}$ place the amplifier in Shutdown, turn off all internal regulators.
GVDD	18	P	Gate drive internal regulator output. This pin must not be used to drive external devices
AVDD	19	P	Internally regulated 5-V analog supply voltage. This pin must not be used to drive external devices
AGND	20	P	Analog ground
PVDD	3	P	PVDD voltage input
	4	P	
	21	P	
	22	P	
PGND	25	P	Ground reference for power device circuitry. Connect this pin to system ground.
	26	P	
	31	P	
	32	P	
OUT_B+	23	O	Positive pin for differential speaker amplifier output B
BST_B+	24	P	Connection point for the OUT_B+ bootstrap capacitor which is used to create a power supply for the high-side gate drive for OUT_B+
OUT_B-	27	O	Negative pin for differential speaker amplifier output B
BST_B-	28	P	Connection point for the OUT_B- bootstrap capacitor which is used to create a power supply for the high-side gate drive for OUT_B-
BST_A-	29	P	Connection point for the OUT_A- bootstrap capacitor which is used to create a power supply for the high-side gate drive for OUT_A-
OUT_A-	30	O	Negative pin for differential speaker amplifier output A
BST_A+	1	P	Connection point for the OUT_A+ bootstrap capacitor which is used to create a power supply for the high-side gate drive for OUT_A+
OUT_A+	2	O	Positive pin for differential speaker amplifier output A
PowerPAD™		P	Connect to the system Ground

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7 Specifications

7.1 Absolute Maximum Ratings

Free-air room temperature 25°C (unless otherwise noted) (1)

		MIN	MAX	UNIT
DVDD	Low-voltage digital supply	–0.3	3.9	V
PVDD	PVDD supply	–0.3	30	V
$V_{I(DigIn)}$	DVDD referenced digital inputs (2)	–0.5	V_{DVDD} + 0.5	V
$V_{I(SPK\_OUTxx)}$	Voltage at speaker output pins	–0.3	32	V
T_A	Ambient operating temperature,	–25	85	°C
T_{stg}	Storage temperature	–40	125	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. Theseare stress ratings only, which do not imply functional operation of the device at these or anyother conditions beyond those indicated under *Recommended OperatingConditions*. Exposure to absolute-maximum-rated conditions for extended periods mayaffect device reliability.
(2) DVDD referenced digital pins include: ADR, GPIO0, GPIO1,GPIO2, LRCLK, SCLK, SDIN,,SCL, SDA, $\overline{PDN}$

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±500	

(1) JEDEC document JEP155 states that 500-V HBM allows safemanufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safemanufacturing with a standard ESD control process.

7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
$V_{(POWER)}$	Power supply inputs	DVDD	1.62		3.63	V
		PVDD	4.5		26.4	
R_{SPK}	Minimum speaker load	BTL Mode	3.2	4		Ω
		PBTL Mode	1.6	2		Ω
L_{OUT}	Minimum inductor value in LC filter under short-circuit condition		1	4.7		µH

7.4 Thermal Information

THERMAL METRIC (1)		TAS5825M VQFN (RHB) 32 PINS			UNIT
		JEDEC STANDARD 2-LAYER PCB	JEDEC STANDARD 4-LAYER PCB	TAS5825MEVM-4 4-LAYER PCB	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	N/A	30.0	24.1	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	N/A	19.1	19.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	N/A	9.9	9.9	°C/W
ψ_{JT}	Junction-to-top characterization parameter	N/A	0.2	0.9	°C/W
ψ_{JB}	Junction-to-board characterization parameter	N/A	10.5	8.8	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	°C/W

(1) For more information about traditional and new thermalmetrics, see the *Semiconductor and ICPackage Thermal Metrics* application report.

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7.5 Electrical Characteristics

Free-air room temperature 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DIGITAL I/O						
|IIH|	Input logic high current level for DVDD referenced digital input pins	$V_{IN(DigIn)} = V_{DVDD}$			10	µA
|IIL|	Input logic low current level for DVDD referenced digital input pins	$V_{IN(DigIn)}$ = 0 V			–10	µA
$V_{IH(Digin)}$	Input logic high threshold for DVDD referenced digital inputs		70%			V_{DVDD}
$V_{IL(Digin)}$	Input logic low threshold for DVDD referenced digital inputs				30%	V_{DVDD}
$V_{OH(Digin)}$	Output logic high voltage level	I_{OH} = 4 mA	80%			V_{DVDD}
$V_{OL(Digin)}$	Output logic low voltage level	I_{OH} = –4 mA			20%	V_{DVDD}
I^2C CONTROL PORT						
$C_{L(I2C)}$	Allowable load capacitance for each I^2C Line				400	pF
$f_{SCL(fast)}$	Support SCL frequency	No wait states, fast mode			400	kHz
$f_{SCL(slow)}$	Support SCL frequency	No wait states, slow mode			100	kHz
SERIAL AUDIO PORT						
t_{DLY}	Required LRCK/FS to SCLK rising edge delay		5			ns
D_{SCLK}	Allowable SCLK duty cycle		40%		60%	
f_S	Supported input sample rates		32		192	kHz
f_{SCLK}	Supported SCLK frequencies		32		64	f_S
f_{SCLK}	SCLK frequency				24.576	MHz
SPEAKER AMPLIFIER (ALL OUTPUT CONFIGURATIONS)						
t_{off}	Turn-off Time	Excluding volume ramp			10	ms
I_{CC}	Quiescent supply current	$\overline{PDN}$=2V, PVDD=13.5V, No Load, LC filter = 10uH + 0.68uF, Fsw = 384kHz, Output Hiz Mode		8.57		mA
I_{CC}	Quiescent supply current	$\overline{PDN}$=2V, PVDD=13.5V, No Load, LC filter = 10uH + 0.68uF, Fsw = 384kHz, Sleep Mode		4.76		mA
I_{CC}	Quiescent supply current	$\overline{PDN}$=2V, PVDD=13.5V, No Load, LC filter = 10uH + 0.68uF,Fsw = 384khz, Deep Sleep Mode		9.2		uA
I_{CC}	Quiescent supply current	$\overline{PDN}$=0.8V, PVDD=13.5V, No Load, LC filter = 10uH + 0.68uF,Fsw = 384khz, Shutdown Mode		1.9		uA
$A_{V(SPK\_AMP)}$	Programmable Gain	Value represents the "peak voltage" disregarding clipping due to lower PVDD). Measured at 0 dB input (1FS)	4.87		29.5	V
$\Delta A_{V(SPK\_AMP)}$	Amplifier gain error	Gain = 29.5 Vp		0.5		dB
f_{SPK_AMP}	Switching frequency of the speaker amplifier			384		kHz
				768		kHz
$R_{DS(on)}$	Drain-to-source on resistance of the individual output MOSFETs	FET + Metallization.		90		mΩ
OCE_{THRES}	Over-Current Error Threshold	Any short to supply, ground, or other channels		7.5		A
	Over-Current cycle-by-cycle limit			6.5		A
$OVE_{THRES(PVDD}$	PVDD over voltage error threshold			28		V
$UVE_{THRES(PVDD}$	PVDD under voltage error threshold			4.2		V
OTE_{THRES}	Over temperature error threshold			160		°C
$OTE_{Hystersis}$	Over temperature error hysteresis			10		°C

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Electrical Characteristics (continued)

Free-air room temperature 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
OTW_{THRES}	Over temperature warning level 1	Read by register 0x73 bit0		112		°C
OTW_{THRES}	Over temperature warning level 2	Read by register 0x73 bit1		122		°C
OTW_{THRES}	Over temperature warning level 3	Read by register 0x73 bit2		134		°C
OTW_{THRES}	Over temperature warning level 4	Read by register 0x73 bit3		146		°C
SPEAKER AMPLIFIER (STEREO BTL)						
$\|V_{OS}\|$	Amplifier offset voltage	Measured differentially with zero input data, programmable gain configured with 29.5 Vp gain, V_{PVDD} = 24 V	–5		5	mV
$P_{O(SPK)}$	Output Power (Per Channel)	V_{PVDD} = 14.4 V, SPK_GAIN = 29.5 Vp, R_{SPK} = 6 Ω, f = 1 KHz THD+N = 10%		17.8		W
		V_{PVDD} = 14.4 V, SPK_GAIN = 29.5 Vp, R_{SPK} = 6 Ω, f = 1 KHz THD+N = 1%		14.5		W
		V_{PVDD} = 24 V, SPK_GAIN = 29.5 Vp, R_{SPK} = 8 Ω, f = 1 KHz THD+N = 10%		38		W
		V_{PVDD} = 24 V, SPK_GAIN = 29.5 Vp, R_{SPK} = 8 Ω, f = 1 KHz THD+N = 1%		30		W
$THD+N_{SPK}$	Total harmonic distortion and noise (P_O = 1 W, f = 1 KHz, R_{SPK} = 6 Ω)	V_{PVDD} = 12 V, SPK_GAIN = 20.9 Vp, LC-filter		0.04%		
		V_{PVDD} = 24 V, SPK_GAIN = 29.5 Vp, LC-filter		0.04%		
$I_{CN(SPK)}$	Idle channel noise(A-weighted, AES17)	V_{PVDD} = 12 V, LC-filter, Load = 6 Ω		40.5		µVrms
		V_{PVDD} = 24 V, LC-filter ,Load = 6 Ω		42.5		
DR	Dynamic range	A-Weighted, -60 dBFS method. P_{VDD} = 24 V, SPK_GAIN = 29.5 Vp		111		dB
SNR	Signal-to-noise ratio	A-Weighted, referenced to 1% THD+N Output Level, PVDD = 24 V		111		dB
		A-Weighted, referenced to 1% THD+N Output Level, PVDD = 14.4 V		107.5		dB
K_{SVR}	Power supply rejection ratio	Injected Noise = 1 KHz, 1 V_{rms}, P_{VDD} = 14.4 V, input audio signal = digital zero		72		dB
$X\text{-}talk_{SPK}$	Cross-talk (worst case between left-to-right and right-to-left coupling)	f = 1 KHz		TBD		dB
SPEAKER AMPLIFIER (MONO PBTL)						
$\|V_{OS}\|$	Amplifier offset voltage	Measured differentially with zero input data, programmable gain configured with 29.5 Vp gain, V_{PVDD} = 24 V	–5		5	mV
$P_{O(SPK)}$	Output Power	V_{PVDD} = 19 V, SPK_GAIN = 29.5 Vp, R_{SPK} = 3 Ω, f = 1KHz, THD+N = 1%		50		W
		V_{PVDD} = 19 V, SPK_GAIN = 29.5 Vp, R_{SPK} = 3 Ω, f = 1KHz, THD+N = 10%		60		W
		V_{PVDD} = 24 V, SPK_GAIN = 29.5 Vp, R_{SPK} = 4 Ω, f = 1KHz, THD+N = 1%		62		W
		V_{PVDD} = 24 V, SPK_GAIN = 29.5 Vp, R_{SPK} = 4 Ω, f = 1KHz, THD+N = 10%		77		W
$THD+N_{SPK}$	Total harmonic distortion and noise (P_O = 1 W, f = 1 KHz	V_{PVDD} = 19 V, SPK_GAIN = 20.9 Vp, LC-filter R_{SPK} = 3 Ω)		0.04%		
		V_{PVDD} = 24 V, SPK_GAIN = 29.5 Vp, LC-filter R_{SPK} = 4 Ω)		0.04%		
DR	Dynamic range	A-Weighted, -60 dBFS method, PVDD=19V		108		dB
SNR	Signal-to-noise ratio	A-Weighted, referenced to 1% THD+N Output Level, PVDD = 19 V		108		dB
		A-Weighted, referenced to 1% THD+N Output Level, PVDD = 24 V		110		dB
K_{SVR}	Power supply rejection ratio	Injected Noise = 1 KHz, 1 V_{rms}, P_{VDD} = 19 V, input audio signal = digital zero		TBD		dB

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7.6 Timing Requirements

		MIN	NOM	MAX	UNIT
Serial Audio Port Timing – Slave Mode					
f_{SCLK}	SCLK frequency	1.024			MHz
t_{SCLK}	SCLK period	40			ns
t_{SCLKL}	SCLK pulse width, low	16			ns
t_{SCLKH}	SCLK pulse width, high	16			ns
t_{SL}	SCLK rising to LRCK/FS edge	8			ns
t_{LS}	LRCK/FS Edge to SCLK rising edge	8			ns
t_{SU}	Data setup time, before SCLK rising edge	8			ns
t_{DH}	Data hold time, after SCLK rising edge	8			ns
t_{DFS}	Data delay time from SCLK falling edge			15	ns
I^2C Bus Timing – Standard					ns
f_{SCL}	SCL clock frequency			100	kHz
t_{BUF}	Bus free time between a STOP and START condition	4.7			µs
t_{LOW}	Low period of the SCL clock	4.7			µs
t_{HI}	High period of the SCL clock	4			µs
t_{RS-SU}	Setup time for (repeated) START condition	4.7			µs
t_{S-HD}	Hold time for (repeated) START condition	4			µs
t_{D-SU}	Data setup time	250			ns
t_{D-HD}	Data hold time	0		900	ns
t_{SCL-R}	Rise time of SCL signal	$20 + 0.1C_B$		1000	ns
t_{SCL-R1}	Rise time of SCL signal after a repeated START condition and after an acknowledge bit	$20 + 0.1C_B$		1000	ns
t_{SCL-F}	Fall time of SCL signal	$20 + 0.1C_B$		1000	ns
t_{SDA-R}	Rise time of SDA signal	$20 + 0.1C_B$		1000	ns
t_{SDA-F}	Fall time of SDA signal	$20 + 0.1C_B$		1000	ns
t_{P-SU}	Setup time for STOP condition	4			µs
I^2C Bus Timing – Fast					
f_{SCL}	SCL clock frequency			400	kHz
t_{BUF}	Bus free time between a STOP and START condition	1.3			µs
t_{LOW}	Low period of the SCL clock	1.3			µs
t_{HI}	High period of the SCL clock	600			ns
t_{RS-SU}	Setup time for (repeated)START condition	600			ns
t_{RS-HD}	Hold time for (repeated)START condition	600			ns
t_{D-SU}	Data setup time	100			ns
t_{D-HD}	Data hold time	0		900	ns
t_{SCL-R}	Rise time of SCL signal	$20 + 0.1C_B$		300	ns
t_{SCL-R1}	Rise time of SCL signal after a repeated START condition and after an acknowledge bit	$20 + 0.1C_B$		300	ns
t_{SCL-F}	Fall time of SCL signal	$20 + 0.1C_B$		300	ns
t_{SDA-R}	Rise time of SDA signal	$20 + 0.1C_B$		300	ns
t_{SDA-F}	Fall time of SDA signal	$20 + 0.1C_B$		300	ns
t_{P-SU}	Setup time for STOP condition	600			ns
t_{SP}	Pulse width of spike suppressed			50	ns

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7.7 Parametric Measurement Information

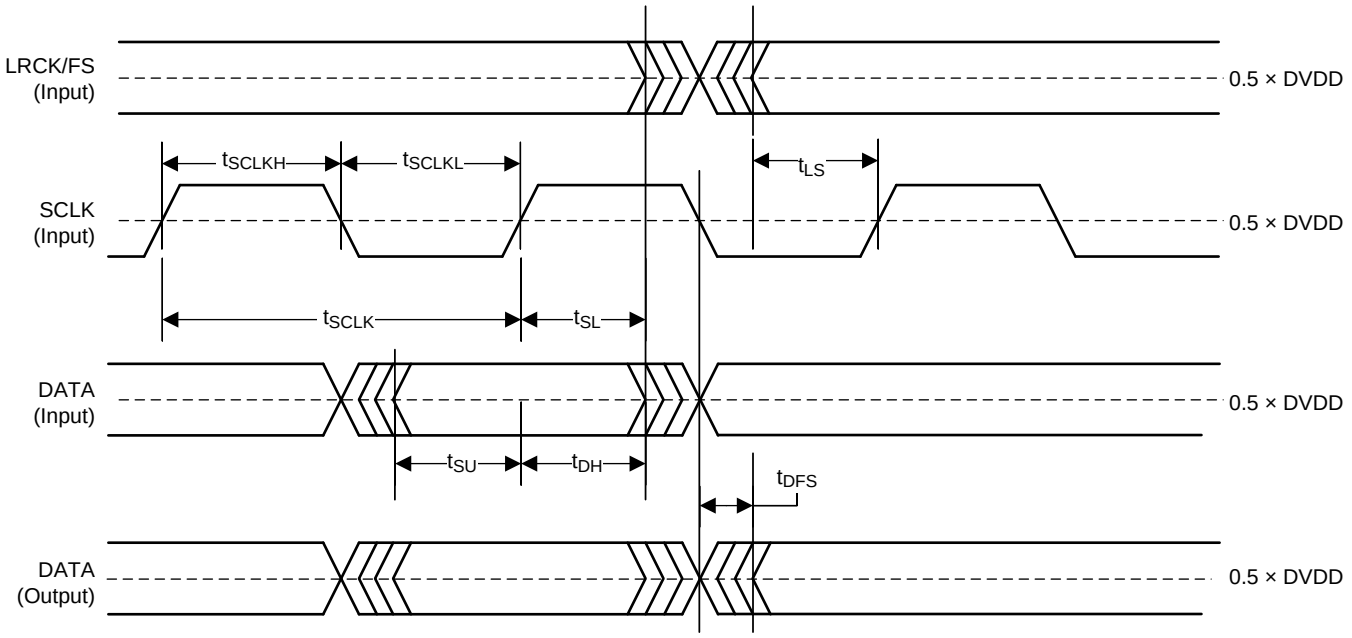

Figure 1. Serial Audio Port Timing in Slave Mode

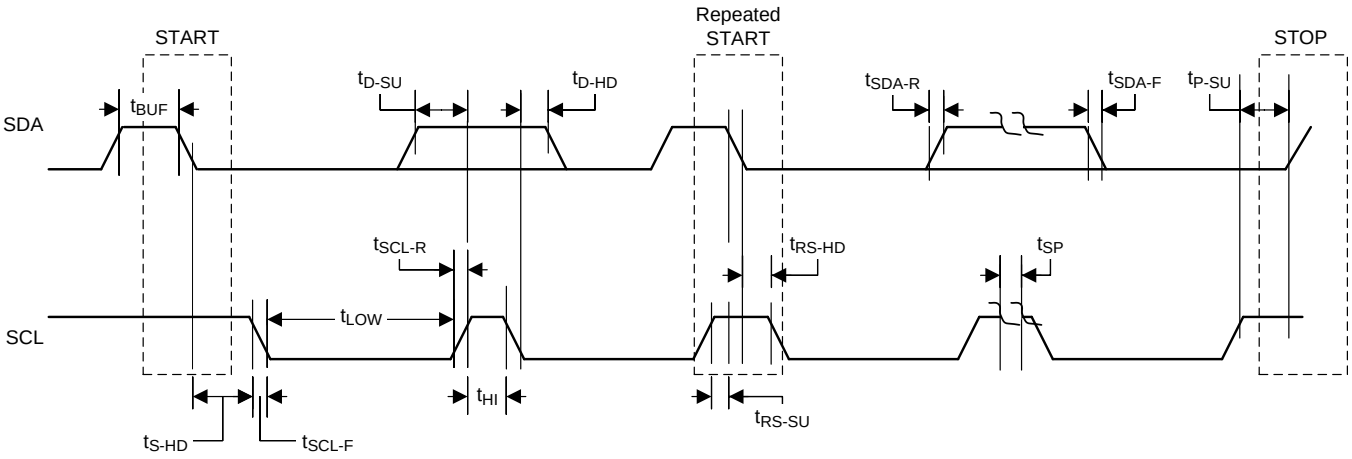

Figure 2. I²C Communication Port Timing Diagram

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8 Detailed Description

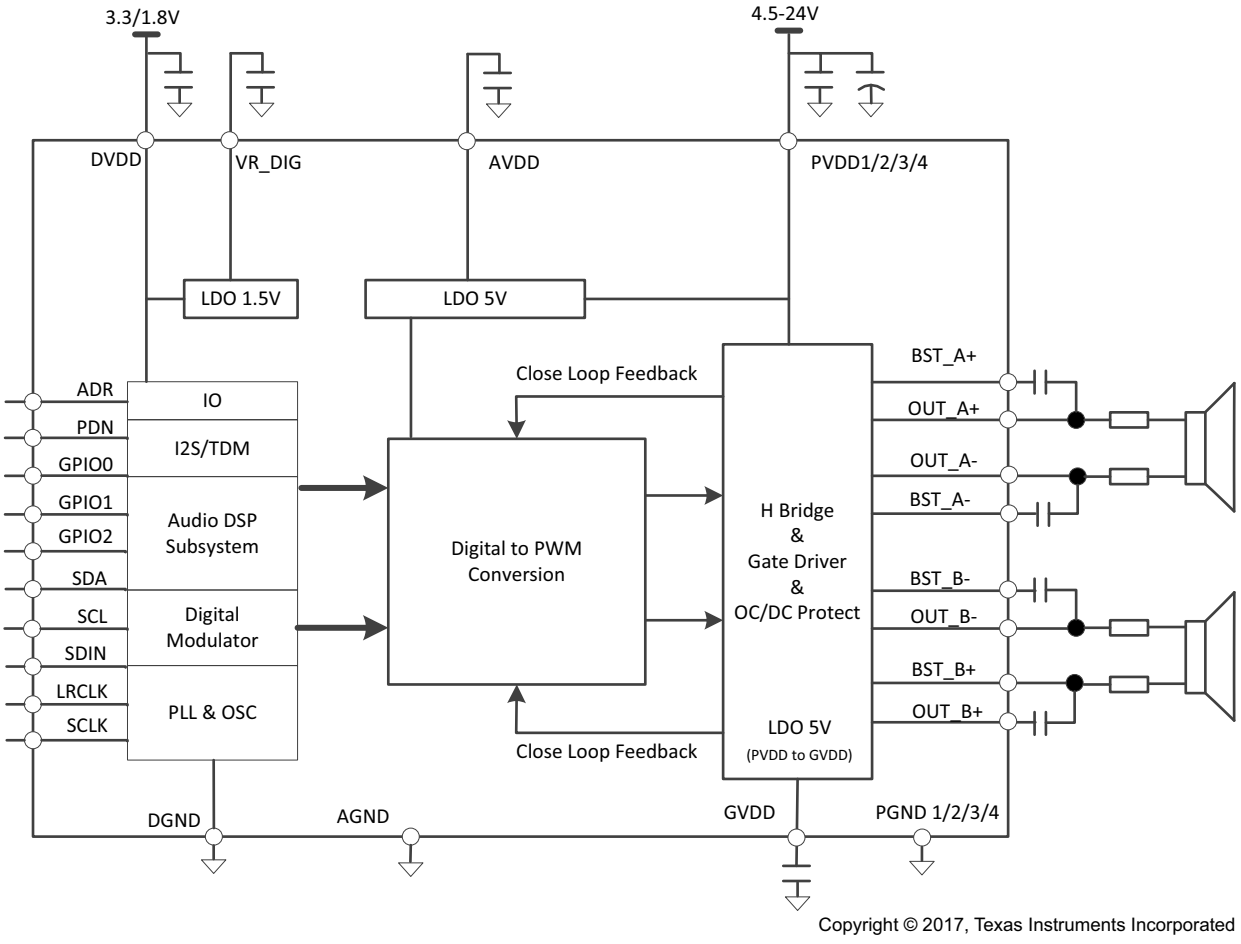
8.1 Overview

The TAS5825M device integrates 4 main building blocks together into a single cohesive device that maximizes sound quality, flexibility, and ease of use. The 4 main building blocks are listed as follows:

- A stereo digital to PWM modulator.
- An Audio DSP subsystem.
- A flexible close-loop amplifier capable of operating in stereo or mono, at several different switching frequencies, and with a variety of output voltages and loads.
- An I^2C control port for communication with the device

The device requires only two power supplies for proper operation. A DVDD supply is required to power the low voltage digital circuitry. Another supply, called PVDD, is required to provide power to the output stage of the audio amplifier. Two internal LDOs convert PVDD to 5 V for GVDD and AVDD.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Power Supplies

To facilitate system design, TAS5825M needs only a 3.3-V or 1.8-V supply in addition to the (typical) 12 V or 24 V power-stage supply. Two internal voltage regulators provide suitable voltage levels for the gate drive circuitry and internal circuitry. The external pins are provided only as a connection point for off-chip bypass capacitors to filter the supply. Connecting external circuitry to these regulator outputs may result in reduced performance and damage to the device. Additionally, all circuitry requiring a floating voltage supply, e.g., the high-side gate drive, is accommodated by built-in bootstrap circuitry requiring only a few external capacitors. In order to provide good electrical and acoustical characteristics, the PWM signal path for the output stage is designed as identical, independent half-bridges. For this reason, each half-bridge has separate bootstrap pins (BST_x). The gate drive voltages (GVDD) are derived from the PVDD voltage. Special attention should be paid to placing all decoupling capacitors as close to their associated pins as possible. In general, inductance between the power-supply pins and decoupling capacitors must be avoided. For a properly functioning bootstrap circuit, a small ceramic capacitor must be connected from each bootstrap pin (BST_x) to the power-stage output pin (OUT_x). When the power-stage output is low, the bootstrap capacitor is charged through an internal diode connected between the gate-drive regulator output pin (GVDD) and the bootstrap pin. When the power-stage output is high, the bootstrap capacitor potential is shifted above the output potential and thus provides a suitable voltage supply for the high-side gate driver.

8.3.2 Device Clocking

The TAS5825M devices have flexible systems for clocking. Internally, the device requires a number of clocks, mostly at related clock rates to function correctly. All of these clocks can be derived from the Serial Audio Interface.

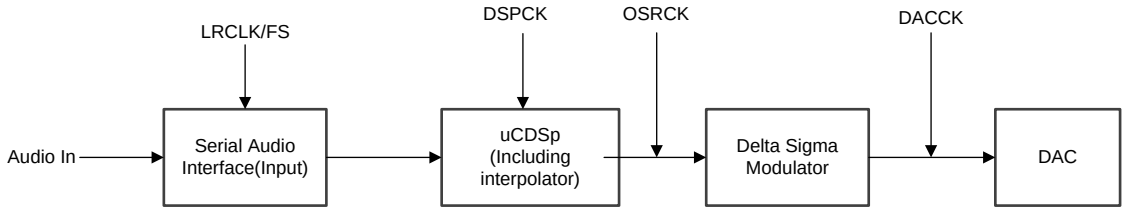


Figure 3. Audio Flow with Respective Clocks

Figure 3 shows the basic data flow and clock Distribution.

The Serial Audio Interface typically has 3 connection pins which are listed as follows:

- SCLK (Bit Clock)
- LRCLK/FS (Left Right Word Clock and Frame Sync)
- SDIN (Input Data)

The device has an internal PLL that is used to take SCLK and create the higher rate clocks required by the DSP and the DAC clock.

The TAS5825M device has an audio sampling rate detection circuit that automatically senses which frequency the sampling rate is operating. Common audio sampling frequencies of 32 kHz, 44.1kHz – 48 kHz, 88.2 kHz – 96 kHz, 176.4 kHz – 192 kHz with ±5% tolerance are supported. The sampling frequency detector sets the clock for DAC and DSP automatically.

If the input LRCLK/SCLK stopped during music playing, TAS5825M's DSP will switch to sleep state and waiting for the clock recovery (Class D's output will switch to Hiz automatically), once LRCLK/SCLK recovered, TAS5825M will auto recover to the play mode without reloading the DSP code.

8.3.3 Serial Audio Port – Clock Rates

The serial audio interface port is a 3-wire serial port with the signals LRCLK/FS , SCLK , and SDIN. SCLK is the serial audio bit clock, used to clock the serial data present on SDIN into the serial shift register of the audio interface. Serial data is clocked into the TAS5825M device with SCLK. The LRCK/FS pin is the serial audio left/right word clock or frame sync when the device is operated in TDM Mode.

ADVANCE INFORMATION

Feature Description (continued)

Table 1. Audio Data Formats, Bit Depths and Clock Rates

FORMAT	DATA BITS	MAXIMUM LRCLK/FS FREQUENCY (kHz)	SCLK RATE (f_S)
I^2S/LJ/RJ	32, 24, 20, 16	Up to 192	64, 32
TDM	32, 24, 20, 16	Up to 48	128,256,512
		96	128,256
		192	128

When any kind of clock error, Out of Range, SCLK-FSYNC Ratio, or Clock halt is detected, the device puts all channels into the Hi-Z state and report Clock Error in Register 113 (Register Address 0x71). When all audio clocks are within the expected range, the device automatically return to the state it was in, but the clock error flag in register 113 need to cleared by Register 120 (Register Address 0x78) manually .

8.3.4 Serial Audio Port - Data Formats and Bit Depths

The device supports industry-standard audio data formats, including standard I2S, left-justified, right-justified and TDM/DSP data. Data formats are selected via Register (Register Address 0x33h -D[5:4]). If the high width of LRCLK/FS in TDM/DSP mode is less than 8 cycles of SCK, the register (Register Address 0x33h -D[3:2]) should set to 01. All formats require binary two's complement, MSB-first audio data; up to 32-bit audio data is accepted. All the data formats, word length and clock rate supported by this device are shown in Table 1. The data formats are detailed in Figure 4 through Figure 8. The word length are selected via Register (Register Address 0x33h -D[1:0]). The offsets of data are selected via Register (Register Address 0x33h -D[7]) and Register (Register Address 0x34h -D[7:0]). Default setting is I2S and 24 bit word length.

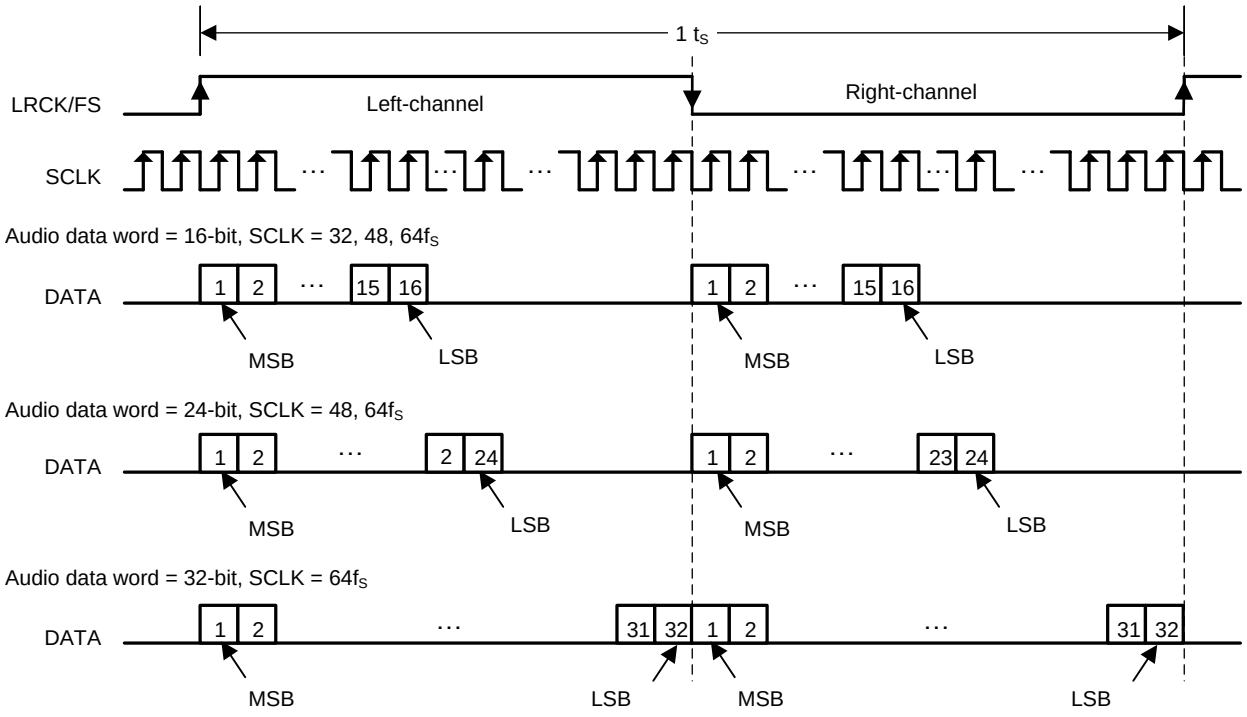
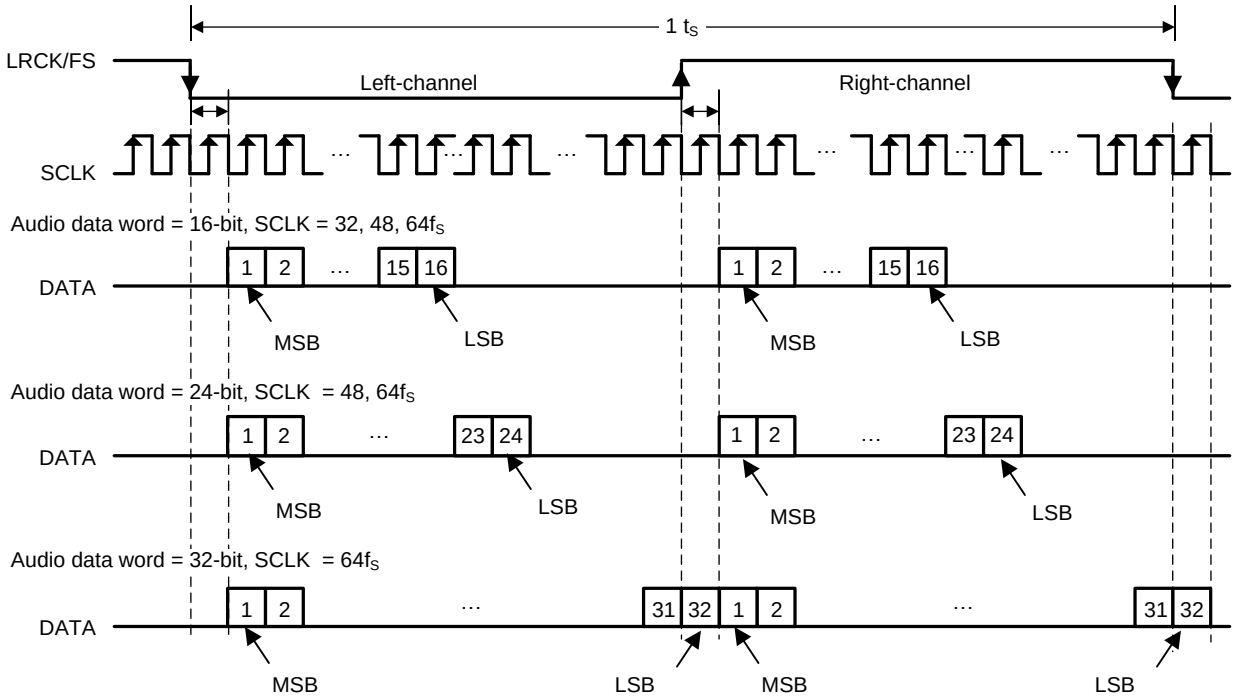
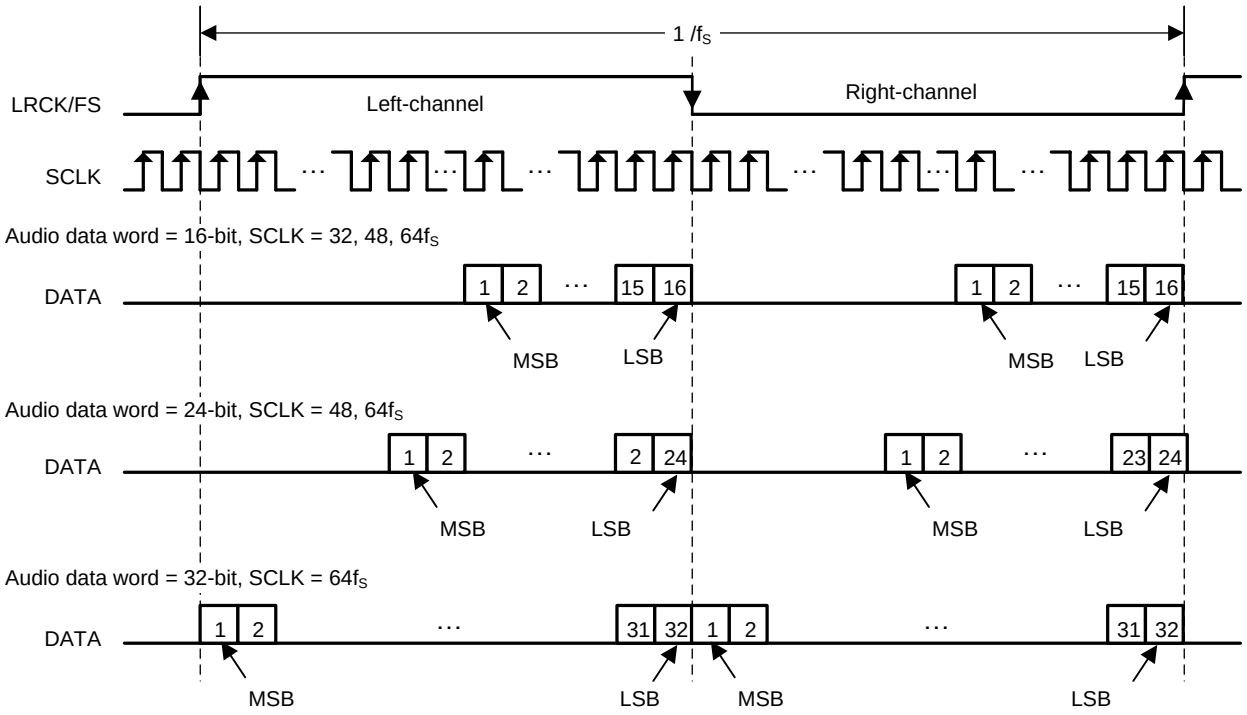


Figure 4. Left Justified Audio Data Format



I^2S Data Format; L-channel = LOW, R-channel = HIGH

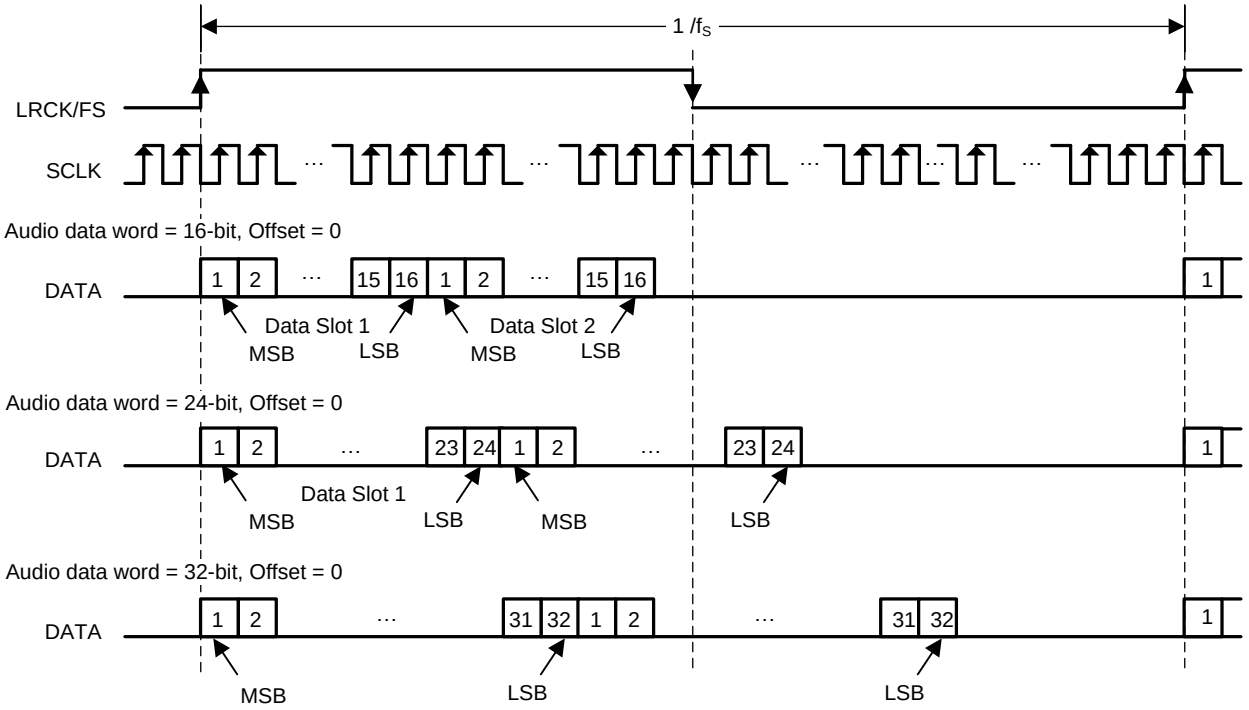
Figure 5. I^2S Audio Data Format



Right Justified Data Format; L-channel = HIGH, R-channel = LOW

Figure 6. Right Justified Audio Data Format

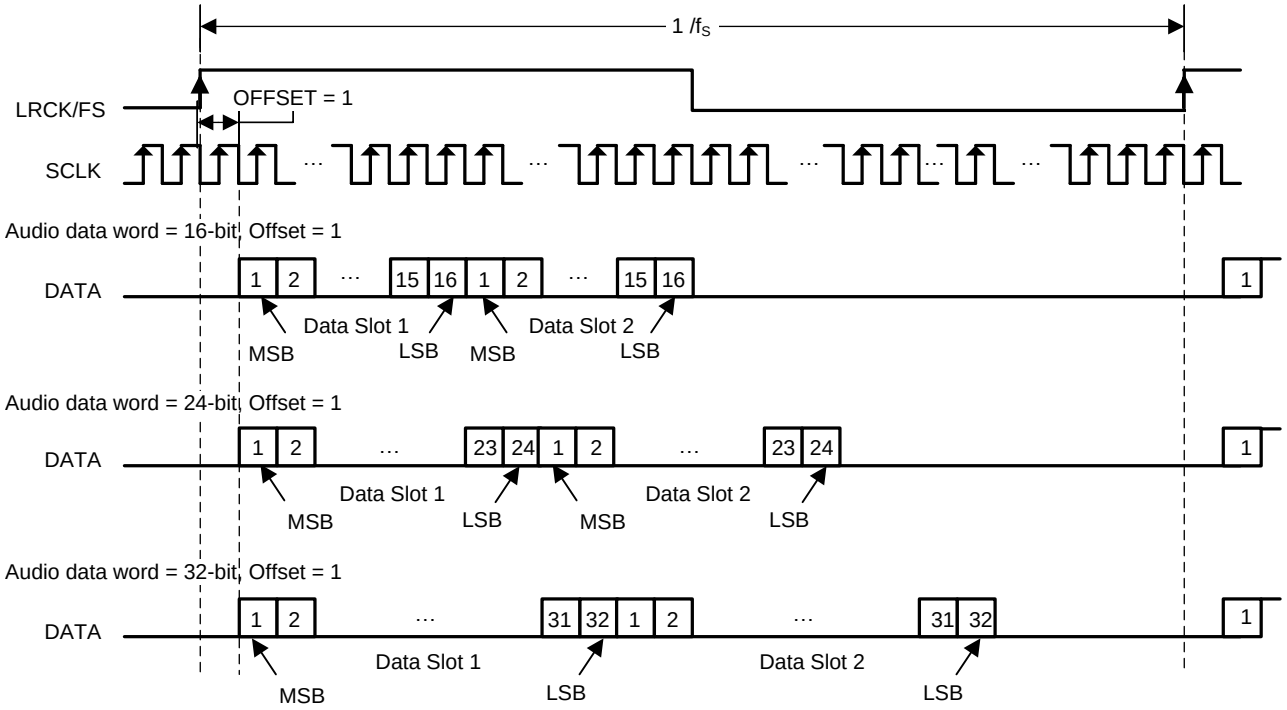
ADVANCE INFORMATION



TDM Data Format with OFFSET = 0

In TDM Modes, Duty Cycle of LRCK/FS should be 1x SCLK at minimum. Rising edge is considered frame start.

Figure 7. TDM 1 Audio Data Format



TDM Data Format with OFFSET = 1

In TDM Modes, Duty Cycle of LRCK/FS should be 1x SCLK at minimum. Rising edge is considered frame start.

Figure 8. TDM 2 Audio Data Format

The I2S slave timing is shown in .

8.3.5 Digital Audio Processing

TAS5825M DSP has flexible process flows for different applications, refer to application note, *TAS5825M Process Flows* for details.

8.3.6 Class D Audio Amplifier

Following the digital clipper, the interpolated audio data is next sent to the Closed Loop Class-D amplifier, whose first stage is Digital to PWM Conversion (DPC) block. In this block, the stereo audio data is translated into two pairs of complimentary pulse width modulated (PWM) signals which are used to drive the outputs of the speaker amplifier. Feedback loops around the DPC ensure constant gain across supply voltages, reduce distortion, and increase immunity to power supply injected noise and distortion. The analog gain is also applied in the Class-D amplifier section of the device. The gain structures are discussed in detail below for both Figure 9 and Table 2. The switching rate of the amplifier is configurable by register (Register Address 0x02h -D[6:4])

8.3.6.1 Speaker Amplifier Gain Select

A combination of digital gain and analog gain is used to provide the overall gain of the speaker amplifier. As seen in Figure 9, the audio path of the TAS5825M consists of a digital audio input port, a digital audio path, a digital to PWM converter (DPC), a gate driver stage, a Class D power stage, and a feedback loop which feeds the output information back into the DPC block to correct for distortion sensed on the output pins. The total amplifier gain is comprised of digital gain, shown in the digital audio path and the analog gain from the input of the analog modulator to the output of the speaker amplifier power stage.

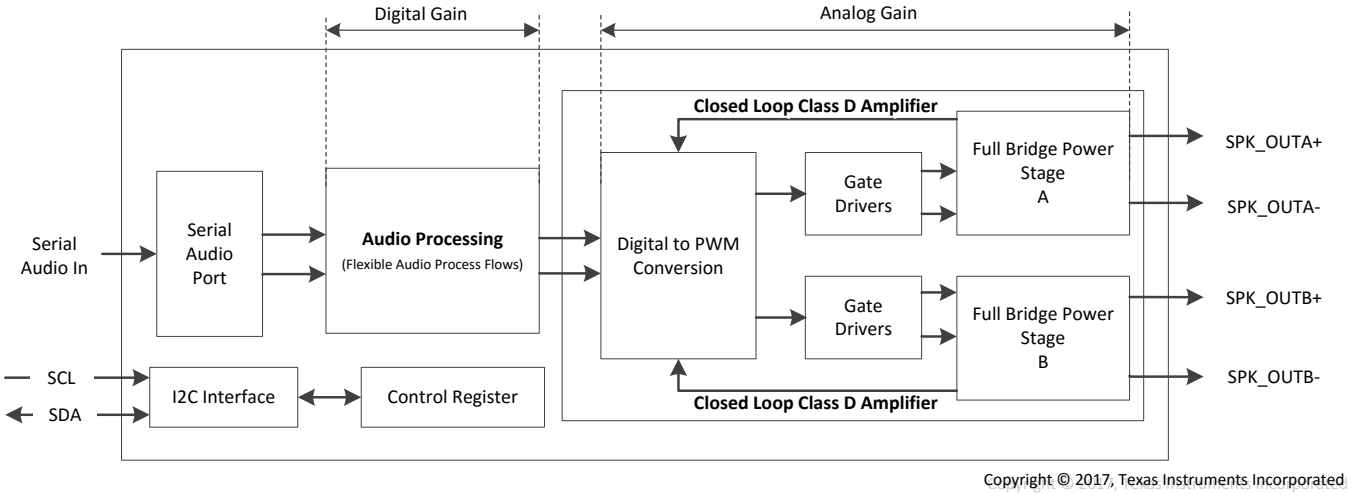


Figure 9. Speaker Amplifier Gain

As shown in Figure 9, the first gain stage for the speaker amplifier is present in the digital audio path. It consists of the volume control and the digital boost block. The volume control is set to 0dB by default, it does not change. For all settings of the register 0x54, AGAIN[4:0], the digital boost block remains at 0 dB. These gain settings ensure that the output signal is not clipping at different PVDD levels. 0dBFS output is 29.5-V peak output voltage

Table 2. Analog Gain Setting

AGAIN <4:0>	GAIN (dBFS)	AMPLIFIER OUTPUT PEAK VOLTAGE (V)
00000	0	29.5
00001	-0.5	27.85
…….	……..	…….
11111	-15.5	4.95

ADVANCE INFORMATION

8.4 Device Functional Modes

8.4.1 Software Control

The TAS5825M device is configured via an I^2 C communication port.

The I2C Communication Protocol is detailed in the I^2C Communication Port section. The I^2C timing requirements are described in the I^2C Bus Timing – Standard and I^2C Bus Timing – Fast sections.

There are two methods to program TAS5825M DSP memory. Loading with I^2C Communication Port by host processor or fast loading from external EEPROM with SPI communication Port. TAS525M supports to load the DSP memory data from external EEPROM via SPI. The GPIOs can be configured as SI,SO and SCK for EEPROM via Register (0x60,0x61,0x62,0x63,0x64). The chip selection $\overline{CS}$ of EEPROM is controlled by the Host Processor. For more information about EEPROM Fast boot loader, see Application note: Program TAS5825M DSP memory from external EEPROM.

8.4.2 Speaker Amplifier Operating Modes

The TAS5825M device can be used with two different amplifier configurations, can be configured by Register 0x02h -D[2]:

- BTL Mode
- PBTL Mode

8.4.2.1 BTL Mode

The familiar BTL mode of operation uses the TAS5825M device to amplify two independent signals, which represent the left and right portions of a stereo signal. The amplified left signal is presented on differential output pair shown as OUT_A+ and OUT_A-, the amplified right signal is presented on differential output pair shown as OUT_B+ and OUT_B-.

8.4.2.2 PBTL Mode

The PBTL mode of operation is used to describe operation in which the two outputs of the device are placed in parallel with one another to increase the power sourcing capabilities of the device. On the output side of the TAS5825M device, the summation of the devices can be done before the filter in a configuration called Pre-Filter Parallel Bridge Tied Load (PBTL). However, the two outputs can be required to merge together after the inductor portion of the output filter. Doing so does require two additional inductors, but allows smaller, less expensive inductors to be used because the current is divided between the two inductors. The process is called Post-Filter PBTL. On the input side of the TAS5825M device, the input signal to the PBTL amplifier is left frame of I2S or TDM data.

8.4.3 Device State Control

Except Shutdown Mode, TAS5825M has other 4 states for different power dissipation

- Register 0x03h -D[1:0]=00, Device stays in Deep Sleep Mode. In this mode, I^2 C block keep works. This mode can be used to extend the battery life time in some portable speaker application case, once the host processor stopped playing audio for a long time, TAS5825M can be set to Deep Sleep Mode to minimize power dissipation until host processor start playing audio again. Device returns back to Play Mode by setting Register 0x03h -D[1:0] to 11. Compare with Shutdown Mode (Pull $\overline{PDN}$ Low), enter or exit Deep Sleep Mode, DSP keeps active.
- Register 0x03h -D[1:0]=01, Device stays in Sleep Mode. In this mode, I^2 C block, Digital core, DSP Memory , 5V Analog LDO keep works. Compare with Shutdown Mode (Pull $\overline{PDN}$ Low), enter or exit Sleep Mode, DSP keeps active.
- Register 0x03h -D[1:0]=10, Device stays in Hiz Mode. In this mode, Only output driver set to be Hiz state, all other block work normally.
- Register 0x03h -D[1:0]=11, Device stays in Play Mode.

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8.5 Programming and Control

8.5.1 I² C Serial Communication Bus

The device has a bidirectional serial control interface that is compatible with I²C bus protocol and supports 100 and 400-kHz data transfer rates for random and sequential write and read operations as a slave device. Because the TAS5825M register map and DSP memory spans multi pages, the user should change from page to page before writing individual register or DSP memory. Changing from page to page is accomplished via register 0 on each page. This register value selects the page address, from 0 to 255. All registers listed in TAS5825M Datasheet belongs to Page 0

8.5.2 I² C Slave Address

The TAS5825M device has 7 bits for the slave address. The first five bits (MSBs) of the slave address are factory preset to 10011(0x9x). The next two bits of address byte are the device select bits which can be user-defined by ADR pin in Table 3.

Table 3. I² C Slave Address Configuration

ADR PIN Configuration	MSBs					User Define		LSB
0 Ω to GND	1	0	0	1	1	0	0	R/$\overline{W}$
1kΩ to GND	1	0	0	1	1	0	1	R/$\overline{W}$
4.7kΩ to GND	1	0	0	1	1	1	0	R/$\overline{W}$
15kΩ to GND	1	0	0	1	1	1	1	R/$\overline{W}$

8.5.2.1 Random Write

As shown in Figure 10, a single-byte data-write transfer begins with the master device transmitting a start condition followed by the I²C device address and the read/write bit. The read/write bit determines the direction of the data transfer. For a write data transfer, the read/write bit is a 0. After receiving the correct I²C device address and the read/write bit, the device responds with an acknowledge bit. Next, the master transmits the address byte corresponding to the internal memory address being accessed. After receiving the address byte, the device again responds with an acknowledge bit. Next, the master device transmits the data byte to be written to the memory address being accessed. After receiving the data byte, the device again responds with an acknowledge bit. Finally, the master device transmits a stop condition to complete the single-byte data-write transfer.

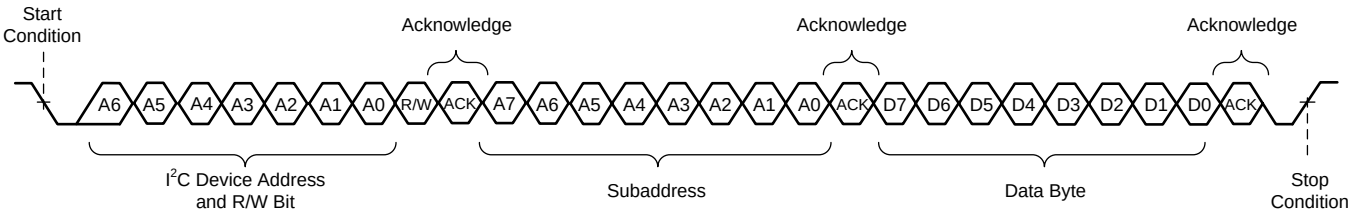

Figure 10. Random Write Transfer

8.5.2.2 Sequential Write

A sequential data-write transfer is identical to a single-byte data-write transfer except that multiple data bytes are transmitted by the master to the device as shown in Figure 11. After receiving each data byte, the device responds with an acknowledge bit and the I² subaddress is automatically incremented by one.

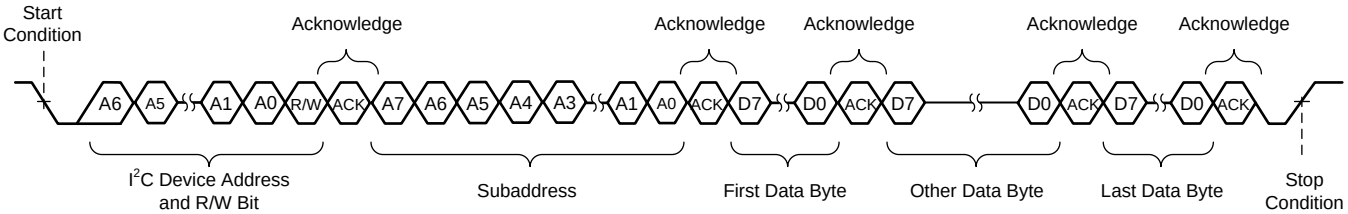

Figure 11. Sequential Write Transfer

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8.5.2.3 Random Read

As shown in Figure 12, a single-byte data-read transfer begins with the master device transmitting a start condition followed by the I^2C device address and the read/write bit. For the data-read transfer, both a write followed by a read are actually done. Initially, a write is done to transfer the address byte of the internal memory address to be read. As a result, the read/write bit is a 0. After receiving the address and the read/write bit, the device responds with an acknowledge bit. In addition, after sending the internal memory address byte, the master device transmits another start condition followed by the address and the read/write bit again. This time the read/write bit is a 1, indicating a read transfer. After receiving the address and the read/write bit, the device again responds with an acknowledge bit. Next, the device transmits the data byte from the memory address being read. After receiving the data byte, the master device transmits a not-acknowledge followed by a stop condition to complete the single-byte data-read transfer.

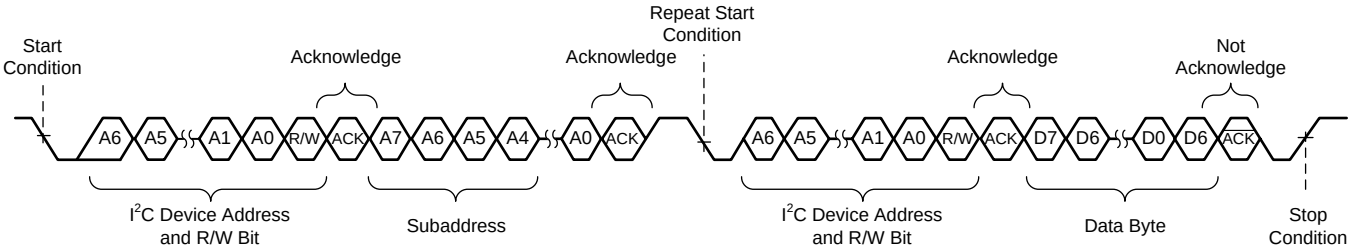

Figure 12. Random Read Transfer

8.5.2.4 Sequential Read

A sequential data-read transfer is identical to a single-byte data-read transfer except that multiple data bytes are transmitted by the device to the master device as shown in Figure 13. Except for the last data byte, the master device responds with an acknowledge bit after receiving each data byte and automatically increments the I^2C sub address by one. After receiving the last data byte, the master device transmits a not-acknowledge followed by a stop condition to complete the transfer.

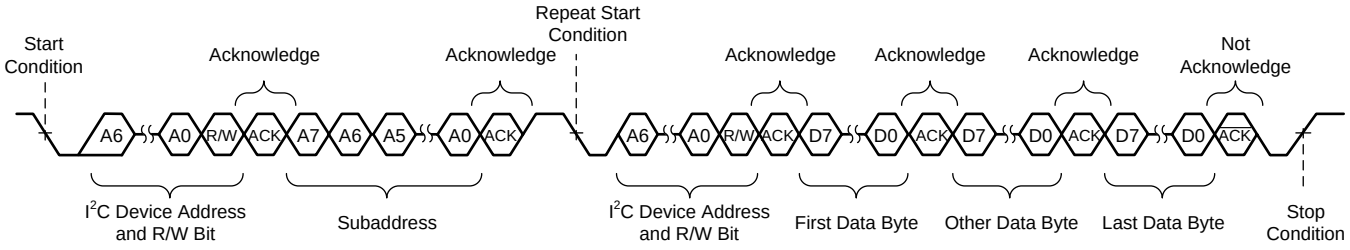

Figure 13. Sequential Read Transfer

8.5.2.5 DSP Memory Book, Page and BQ update

On page 0x00 of each book, register 0x7f is used to change the book. Register 0x00 of each page is used to change the page. To change a book first write 0x00 to register 0x00 to switch to page 0 then write the book number to register 0x7f on page 0. To change between pages in a book, simply write the page number to register 0x00.

All the Biquad Filters coefficients are addressed in book 0xAA. The five coefficients of every Biquad Filter should be written entirely and sequentially from the lowest address to the highest address. The address of all Biquad Filters can be found in Register Maps

All DSP/Audio Process Flow Related Register are listed in Application Note, TAS5825M Process Flows

8.5.2.6 Checksum

This device supports two different check sum schemes, a cyclic redundancy check (CRC) checksum and an Exclusive (XOR) checksum. Register reads do not change checksum, but writes to even nonexistent registers will change the checksum. Both checksums are 8-bit checksums and both are available together simultaneously. The checksums can be reset by writing a starting value (eg. 0x 00 00 00 00) to their respective 4-byte register locations.

8.5.2.6.1 Cyclic Redundancy Check (CRC) Checksum

The 8-bit CRC checksum used is the 0x7 polynomial (CRC-8-CCITT I.432.1; ATM HEC, ISDN HEC and cell delineation, (1 + x1 + x2 + x8)). A major advantage of the CRC checksum is that it is input order sensitive. The CRC supports all I^2C transactions, excluding book and page switching. The CRC checksum is read from register 0x7E on page0 of any book (B_x, Page_0, Reg_126). The CRC checksum can be reset by writing 0x00 to the same register locations where the CRC checksum is valid.

8.5.2.6.2 Exclusive or (XOR) Checksum

The Xor checksum is a simpler checksum scheme. It performs sequential XOR of each register byte write with the previous 8-bit checksum register value. XOR supports only Book 0x8C, and excludes page switching and all registers in Page 0x00 of Book 0x8C. XOR checksum is read from location register 0x7D on page 0x00 of book 0x8C (B_140, Page_0, Reg_125). The XOR Checksum can be reset by writing 0x00 to the same register location where it is read.

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8.5.3 Control via Software

- Startup Procedures
- Shutdown Procedures

8.5.3.1 Startup Procedures

1. Configure ADR pin with proper setting for I^2C device address.
2. Bring up power supplies (it does not matter if PVDD or DVDD comes up first).
3. Start SCLK, LRCLK.
4. Once I^2S clock are stable, configure the device via the I^2C control port based on the user cases (Make sure the $\overline{PDN}$ pin = HIGH before control port operating).
5. The device is now in normal operation.

Note: It is recommended that I^2C control port register changes occur when the device is placed into SLEEP or Hiz mode. This can be accomplished by configuring Register 0x03h -D[1:0] in the control register.

8.5.3.2 Shutdown Procedures

1. The device is in normal operation.
2. Configure the Register 0x03h -D[1:0]=00 (DEEP SLEEP) via the I^2C control port or Pull $\overline{PDN}$ low.
3. The clocks can now be stopped and the power supplies brought down.
4. The device is now fully shutdown and powered off.

8.5.3.3 Protection and Monitoring

8.5.3.3.1 Overcurrent Limit (Cycle-By-Cycle)

The CBC current-limiting circuit terminates each PWM pulse limit the output current flow to the average current limit (I_{LIM}) threshold. The overall effect on the audio in the case of a current overload is quite similar a voltage-clipping event, temporarily limiting power at the peaks of the music signal and normal operation continues without disruption on removal of the overload.

8.5.3.3.2 Overcurrent Shutdown (OCSD)

Under severe short-circuit event, such as a short to PVDD or ground, the device uses a peak-current detector, and the affected channel shuts down in < 100 ns if the peak current are enough. The shutdown speed depends on a number of factors, such as the impedance of the short circuit, supply voltage, and switching frequency. The user may restart the affected channel via I^2C. An OCSD event activates the fault pin, and the I^2 fault register saves a record. If the supply or ground short is strong enough to exceed the peak current threshold but not severe enough to trigger the OSCD, the peak current limiter prevents excess current from damaging the output FETs, and operation returns to normal after the short is removed.

8.5.3.3.3 DC Detect

If the TAS5825M device measures a DC offset in the output voltage, the FAULTZ line is pulled low and the OUTxx outputs transition to high impedance, signifying a fault.

ADVANCE INFORMATION

8.6 Register Maps

8.6.1 CONTROL PORT Registers

Table 4 lists the memory-mapped registers for the CONTROL PORT. All register offset addresses not listed in Table 4 should be considered as reserved locations and the register contents should not be modified.

Table 4. CONTROL PORT Registers

Offset	Acronym	Register Name	Section
1h	RESET_CTRL	Register 1	Go
2h	DEVICE_CTRL_1	Register 2	Go
3h	DEVICE_CTRL2	Register 3	Go
Fh	I2C_PAGE_AUTO_INC	Register 15	Go
28h	SIG_CH_CTRL	Register 40	Go
29h	CLOCK_DET_CTRL	Register 41	Go
31h	I2S_CTRL	Register 49	Go
33h	SAP_CTRL1	Register 51	Go
34h	SAP_CTRL2	Register 52	Go
37h	FS_MON	Register 55	Go
38h	BCK (SCLK)_MON	Register 56	Go
39h	CLKDET_STATUS	Register 57	Go
40h	DSP_PGM_MODE	Register 64	Go
46h	DSP_CTRL	Register 70	Go
4Ch	DIG_VOL	Register 76	Go
4Eh	DIG_VOL_CTRL1	Register 78	Go
4Fh	DIG_VOL_CTRL2	Register 79	Go
50h	AUTO_MUTE_CTRL	Register 80	Go
51h	AUTO_MUTE_TIME	Register 81	Go
53h	ANA_CTRL	Register 83	Go
54h	AGAIN	Register 84	Go
55h	SPI_CLK	Register 85	Go
56h	EEPROM_CTRL0	Register 86	Go
57h	EEPROM_RD_CMD	Register 87	Go
58h	EEPROM_ADDR_START0	Register 88	Go
59h	EEPROM_ADDR_START1	Register 89	Go
5Ah	EEPROM_ADDR_START2	Register 90	Go
5Bh	EEPROM_BOOT_STATUS	Register 91	Go
5Ch	BQ_WR_CTRL1	Register 92	Go
5Eh	ADC_RPT	Register 94	Go
60h	GPIO_CTRL	Register 96	Go
61h	GPIO0_SEL	Register 97	Go
62h	GPIO1_SEL	Register 98	Go
63h	GPIO2_SEL	Register 99	Go
64h	GPIO_INPUT_SEL	Register 100	Go
65h	GPIO_OUT	Register 101	Go
66h	GPIO_OUT_INV	Register 102	Go
67h	DIE_ID	Register 103	Go
68h	POWER_STATE	Register 104	Go
69h	AUTOMUTE_STATE	Register 105	Go
6Ah	PHASE_CTRL	Register 106	Go
6Bh	SS_CTRL0	Register 107	Go

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Table 4. CONTROL PORT Registers (continued)

Offset	Acronym	Register Name	Section
6Ch	SS_CTRL1	Register 108	Go
6Dh	SS_CTRL2	Register 109	Go
6Eh	SS_CTRL3	Register 110	Go
6Fh	SS_CTRL4	Register 111	Go
70h	CHAN_FAULT	Register 112	Go
71h	GLOBAL_FAULT1	Register 113	Go
72h	GLOBAL_FAULT2	Register 114	Go
73h	WARNING	Register 115	Go
74h	PIN_CONTROL1	Register 116	Go
75h	PIN_CONTROL2	Register 117	Go
76h	MISC_CONTROL	Register 118	Go
77h	CBC_CONTROL	Register 119	Go
78h	FAULT_CLEAR	Register 120	Go

Complex bit access types are encoded to fit into small table cells. Table 5 shows the codes that are used for access types in this section.

Table 5. CONTROL PORT Access Type Codes

Access Type	Code	Description
Read Type		
R	R	Read
Write Type		
W	W	Write
Reset or Default Value		
-n		Value after reset or the default value

ADVANCE INFORMATION

8.6.1.1 RESET_CTRL Register (Offset = 1h) [reset = 0x00]

RESET_CTRL is shown in Figure 14 and described in Table 6.

Return to Summary Table.

Figure 14. RESET_CTRL Register

7	6	5	4	3	2	1	0
RESERVED			RST_MOD	RESERVED			RST_REG
R/W			W	R			W

Table 6. RESET_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	This bit is reserved
4	RST_DIG_CORE	W	0	WRITE CLEAR BIT Reset DIG_CORE WRITE CLEAR BIT Reset Full Digital Core. This bit resets the Full Digital Signal Path (Include DSP coefficient RAM and I2C Control Port Registers), Since the DSP is also reset, the coeffient RAM content will also be cleared by the DSP. 0: Normal 1: Reset Full Digital Signal Path
3-1	RESERVED	R	000	This bit is reserved
0	RST_REG	W	0	WRITE CLEAR BIT Reset Registers This bit resets the mode registers back to their initial values. Only reset Control Port Registers, The RAM content is not cleared. 0: Normal 1: Reset I^2C Control Port Registers

ADVANCE INFORMATION

8.6.1.2 DEVICE_CTRL_1 Register (Offset = 2h) [reset = 0x00]

DEVICE_CTRL_1 is shown in Figure 15 and described in Table 7.

Return to Summary Table.

Figure 15. DEVICE_CTRL_1 Register

7	6	5	4	3	2	1	0
RESERVED	FSW_SEL			RESERVED	DAMP_PBTL	DAMP_MOD	
R/W	R/W			R/W	R/W	R/W	

Table 7. DEVICE_CTRL_1 Register Field Descriptions

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6-4	FSW_SEL	R/W	000	SELECT FSW 000:384K 001:260K 010:480K 011:576K 100:768K 101:Reserved 110:Reserved 111:Reserved
3	RESERVED	R/W	0	This bit is reserved
2	DAMP_PBTL	R/W	0	0: SET DAMP TO BTL MODE 1:SET DAMP TO PBTL MODE
1-0	DAMP_MOD	R/W	00	00:BD MODE 01:1SPW MODE 10:HYBRID MODE (Note: HYBRID MODE only work with TAS5825P's process flow)

ADVANCE INFORMATION

8.6.1.3 DEVICE_CTRL2 Register (Offset = 3h) [reset = 00x10]

DEVICE_CTRL2 is shown in Figure 16 and described in Table 8.

Return to Summary Table.

Figure 16. DEVICE_CTRL2 Register

7	6	5	4	3	2	1	0
RESERVED			DIS_DSP	MUTE_LEFT	RESERVED	CTRL_STATE	
R/W			R/W	R/W	R/W	R/W	

Table 8. DEVICE_CTRL2 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	This bit is reserved
4	DIS_DSP	R/W	1	DSP reset When the bit is made 0, DSP will start powering up and send out data. This needs to be made 0 only after all the input clocks are settled so that DMA channels do not go out of sync. 0: Normal operation 1: Reset the DSP
3	MUTE	R/W	0	Mute both Left and Right Channel This bit issues soft mute request for both left and right channel. The volume will be smoothly ramped down/up to avoid pop/click noise. 0: Normal volume 1: Mute
2	RESERVED	R/W	0	This bit is reserved
1-0	CTRL_STATE	R/W	00	device state control register 00: Deep Sleep 01: Sleep 10: Hiz, 11: PLAY

ADVANCE INFORMATION

8.6.1.4 I2C_PAGE_AUTO_INC Register (Offset = Fh) [reset = 0x00]

I2C_PAGE_AUTO_INC is shown in Figure 17 and described in Table 9.

Return to Summary Table.

Figure 17. I2C_PAGE_AUTO_INC Register

7	6	5	4	3	2	1	0
RESERVED				PAGE_AUTOINC_REG	RESERVED		
R/W				R/W	R/W		

Table 9. I2C_PAGE_AUTO_INC Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3	PAGE_AUTOINC_REG	R/W	0	Page auto increment disable Disable page auto increment mode. for non -zero books. When end of page is reached it goes back to 8th address location of next page when this bit is 0. When this bit is 1 it goes to 0 th location of current page itself like in older part. 0: Enable Page auto increment 1: Disable Page auto increment
2-0	RESERVED	R/W	000	This bit is reserved

8.6.1.5 SIG_CH_CTRL Register (Offset = 28h) [reset = 0x00]

SIG_CH_CTRL is shown in Figure 18 and described in Table 10.

Return to Summary Table.

Figure 18. SIG_CH_CTRL Register

7	6	5	4	3	2	1	0
SCLK_RATIO_CONFIGURE				FSMODE	RESERVED		
R/W				R/W	R/W		

Table 10. SIG_CH_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	SCLK_RATIO_CONFIGURE	R/W	0000	These bits indicate the configured SCLK ratio, the number of SCLK clocks in one audio frame. Device will set this ratio automatically. 4'b0011:32FS 4'b0101:64FS 4'b0111:128FS 4'b1001:256FS 4'b1011:512FS
3	FSMODE	R/W	0	FS Speed Mode These bits select the FS operation mode, which must be set according to the current audio sampling rate. Need set it manually If the input Fs is 44.1kHz/88.2kHz/176.4kHz. 4 'b0000 Auto detection 4 'b0100 Reserved 4 'b0110 32KHz 4 'b1000 44.1KHz 4 'b1001 48KHz 4'b1010 88.2KHz 4 'b1011 96KHz 4 'b1100 176.4KHz 4 'b1101 192KHz Others Reserved
2-0	RESERVED	R/W	000	This bit is reserved

ADVANCE INFORMATION

8.6.1.6 CLOCK_DET_CTRL Register (Offset = 29h) [reset = 0x00]

CLOCK_DET_CTRL is shown in Figure 19 and described in Table 11.

Return to Summary Table.

Figure 19. CLOCK_DET_CTRL Register

7	6	5	4	3	2	1	0
RESERVED	DIS_DET_PLL	DIS_DET_SCLK_RANGE	DIS_DET_FS	DIS_DET_SCLK	DIS_DET_MISS	RESERVED	DIS_DET_LOCK
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 11. CLOCK_DET_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6	DIS_DET_PLL	R/W	0	Ignore PLL overate Detection This bit controls whether to ignore the PLL overrate detection. The PLL must be slow than 150MHz or an error will be reported. When ignored, a PLL overrate error will not cause a clock error. 0: Regard PLL overrate detection 1: Ignore PLL overrate detection
5	DIS_DET_SCLK_RANGE	R/W	0	Ignore BCK Range Detection This bit controls whether to ignore the SCLK range detection. The SCLK must be stable between 256KHz and 50MHz or an error will be reported. When ignored, a SCLK range error will not cause a clock error. 0: Regard BCK Range detection 1: Ignore BCK Range detection
4	DIS_DET_FS	R/W	0	Ignore FS Error Detection This bit controls whether to ignore the FS Error detection. When ignored, FS error will not cause a clock error.But CLKDET_STATUS will report fs error. 0: Regard FS detection 1: Ignore FS detection
3	DIS_DET_SCLK	R/W	0	Ignore SCLK Detection This bit controls whether to ignore the SCLK detection against LRCK. The SCLK must be stable between 32FS and 512FS inclusive or an error will be reported. When ignored, a SCLK error will not cause a clock error. 0: Regard SCLK detection 1: Ignore SCLK detection
2	DIS_DET_MISS	R/W	0	Ignore SCLK Missing Detection This bit controls whether to ignore the SCLK missing detection. When ignored an SCLK missing will not cause a clock error. 0: Regard SCLK missing detection 1: Ignore SCLKmissing detection
1	RESERVED	R/W	0	This bit is reserved
0	DIS_DET_LOCK	R/W	0	This bit is reserved

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8.6.1.7 I2S_CTRL Register (Offset = 31h) [reset = 0x00]

I2S_CTRL is shown in Figure 20 and described in Table 12.

Return to Summary Table.

Figure 20. I2S_CTRL Register

7	6	5	4	3	2	1	0
RESERVED		SCLK_INV	RESERVED	RESERVED	RESERVED		RESERVED
R/W		R/W	R/W	R	R		R/W

Table 12. I2S_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	RESERVED	R/W	00	This bit is reserved
5	SCLK_INV	R/W	0	SCLK Polarity This bit sets the inverted SCLK mode. In inverted SCLK mode, the DAC assumes that the LRCK and DIN edges are aligned to the rising edge of the SCLK. Normally they are assumed to be aligned to the falling edge of theSCLK 0: Normal SCLKmode 1: Inverted SCLK mode
4	RESERVED	R/W	0	This bit is reserved
3	RESERVED	R	0	This bit is reserved
2-1	RESERVED	R/W	00	This bit is reserved
0	RESERVED	R/W	0	This bit is reserved

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8.6.1.8 SAP_CTRL1 Register (Offset = 33h) [reset = 0x02]

SAP_CTRL1 is shown in Figure 21 and described in Table 13.

Return to Summary Table.

Figure 21. SAP_CTRL1 Register

7	6	5	4	3	2	1	0
I2S_SHIFT_MSB		DATA_FORMAT		I2S_LRCLK_PULSE		WORD_LENGTH	
R/W		R/W		R/W		R/W	

Table 13. SAP_CTRL1 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	I2S_SHIFT_MSB	R/W	00	I2S Shift MSB
5-4	DATA_FORMAT	R/W	00	I2S Data Format These bits control both input and output audio interface formats for DAC operation. 00: I2S 01: TDM/DSP 10: RTJ 11: LTJ
3-2	I2S_LRCLK_PULSE	R/W	00	01: lrclk pulse < 8 SCLK
1-0	WORD_LENGTH	R/W	10	I2S Word Length These bits control both input and output audio interface sample word lengths for DAC operation. 00: 16 bits 01: 20 bits 10: 24 bits 11: 32 bits

8.6.1.9 SAP_CTRL2 Register (Offset = 34h) [reset = 0x00]

SAP_CTRL2 is shown in Figure 22 and described in Table 14.

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Figure 22. SAP_CTRL2 Register

7	6	5	4	3	2	1	0
I2S_SHIFT							
R/W							

Table 14. SAP_CTRL2 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	I2S_SHIFT	R/W	00000000	I2S Shift LSB These bits control the offset of audio data in the audio frame for both input and output. The offset is defined as the number of SCLK from the starting (MSB) of audio frame to the starting of the desired audio sample. 000000000: offset = 0 SCLK (no offset) 000000001: ofsset = 1 SCLK 000000010: offset = 2 SCLKs and 111111111: offset = 512 SCLKs

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8.6.1.10 FS_MON Register (Offset = 37h) [reset = 0x00]

FS_MON is shown in Figure 23 and described in Table 15.

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Figure 23. FS_MON Register

7	6	5	4	3	2	1	0
RESERVED		SCLK_RATIO_HIGH		FS			
R/W		R		R			

Table 15. FS_MON Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	RESERVED	R/W	00	This bit is reserved
5-4	SCLK_RATIO_HIGH	R	00	2 msbs of detected SCLK ratio
3-0	FS	R	0000	These bits indicate the currently detected audio sampling rate. 4 'b0000 FS Error 4 'b0100 16KHz 4 'b0110 32KHz 4 'b1000 Reserved 4 'b1001 48KHz 4 'b1011 96KHz 4 'b1101 192KHz Others Reserved

8.6.1.11 BCK (SCLK)_MON Register (Offset = 38h) [reset = 0x00]

BCK_MON is shown in Figure 24 and described in Table 16.

Return to Summary Table.

Figure 24. BCK (SCLK)_MON Register

7	6	5	4	3	2	1	0
BCLK (SCLK)_RATIO_LOW							
R							

Table 16. BCK_MON Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	BCLK (SCLK)_RATIO_LOW	R	00000000	These bits indicate the currently detected BCK (SCLK) ratio, the number of BCK (SCLK) clocks in one audio frame. BCK (SCLK) = 32 FS~512 FS

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8.6.1.12 CLKDET_STATUS Register (Offset = 39h) [reset = 0x00]

CLKDET_STATUS is shown in Figure 25 and described in Table 17.

Return to Summary Table.

Figure 25. CLKDET_STATUS Register

7	6	5	4	3	2	1	0
RESERVED		DET_STATUS					
R/W		R					

Table 17. CLKDET_STATUS Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	RESERVED	R/W	00	This bit is reserved
5-0	DET_STATUS	R	000000	bit0: In auto detection mode(reg_fsmode=0),this bit indicated whether the audio sampling rate is valid or not. In non auto detection mode(reg_fsmode!=0), Fs error indicates that configured fs is different with detected fs. Even FS Error Detection Ignore is set, this flag will be also asserted. bit1: This bit indicates whether the SCLK is valid or not. The SCLK ratio must be stable and in the range of 32-512FS to be valid. bit2: This bit indicates whether the SCLK is missing or not. bit3:This bit indicates whether the PLL is locked or not. The PLL will be reported as unlocked when it is disabled. bits4:This bit indicates whether the PLL is overrate bits5:This bit indicates whether the SCLK is overrate or underrate

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8.6.1.13 DSP_PGM_MODE Register (Offset = 40h) [reset = 0x10]

DSP_PGM_MODE is shown in Figure 26 and described in Table 18.

Return to Summary Table.

Figure 26. DSP_PGM_MODE Register

7	6	5	4	3	2	1	0
RESERVED			MODE_SEL				
R/W			R/W				

Table 18. DSP_PGM_MODE Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	This bit is reserved
4-0	MODE_SEL	R/W	10000	DSP Program Selection These bits select the DSP program to use for audio processing. 00000 => ram mode 00001 => rom mode 1 00010 => rom mode 2 00011 => rom mode 3

8.6.1.14 DSP_CTRL Register (Offset = 46h) [reset = 0x01]

DSP_CTRL is shown in Figure 27 and described in Table 19.

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Figure 27. DSP_CTRL Register

7	6	5	4	3	2	1	0
RESERVED			USER_DEFINED_PROCESSING_RATE		RESERVED	BOOT_FROM_IRAM	USE_DEFAULT_COEFFS
R/W			R/W		R	R/W	R/W

Table 19. DSP_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	This bit is reserved
4-3	USER_DEFINED_PROCESSING_RATE	R/W	00	00:input 01:48k 10:96k 11:192k
2	RESERVED	R	0	This bit is reserved
1	RESERVED	R	0	This bit is reserved
0	USE_DEFAULT_COEFFS	R/W	1	Use default coefficients from ZROM this bit controls whether to use default coefficients from ZROM or use the non-default coefficients downloaded to device by the Host 0 : don't use default coefficients from ZROM 1 : use default coefficents from ZROM

8.6.1.15 DIG_VOL Register (Offset = 4Ch) [reset = 30h]

DIG_VOL is shown in Figure 28 and described in Table 20.

Return to Summary Table.

Figure 28. DIG_VOL Register

7	6	5	4	3	2	1	0
PGA_LEFT							
R/W							

Table 20. DIG_VOL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	PGA	R/W	00110000	Digital Volume These bits control both left and right channel digital volume. The digital volume is 24 dB to -103 dB in -0.5 dB step. 00000000: +24.0 dB 00000001: +23.5 dB ..... and 00101111: +0.5 dB 00110000: 0.0 dB 00110001: -0.5 dB ..... 11111110: -103 dB 11111111: Mute

8.6.1.16 DIG_VOL_CTRL1 Register (Offset = 4Eh) [reset = 0x33]

DIG_VOL_CTRL1 is shown in Figure 29 and described in Table 21.

Return to Summary Table.

Figure 29. DIG_VOL_CTRL1 Register

7	6	5	4	3	2	1	0
PGA_RAMP_DOWN_SPEED		PGA_RAMP_DOWN_STEP		PGA_RAMP_UP_SPEED		PGA_RAMP_UP_STEP	
R/W		R/W		R/W		R/W	

Table 21. DIG_VOL_CTRL1 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	PGA_RAMP_DOWN_SPEED	R/W	00	Digital Volume Normal Ramp Down Frequency These bits control the frequency of the digital volume updates when the volume is ramping down. 00: Update every 1 FS period 01: Update every 2 FS periods 10: Update every 4 FS periods 11: Directly set the volume to zero (Instant mute)
5-4	PGA_RAMP_DOWN_STEP	R/W	11	Digital Volume Normal Ramp Down Step These bits control the step of the digital volume updates when the volume is ramping down. 00: Decrement by 4 dB for each update 01: Decrement by 2 dB for each update 10: Decrement by 1 dB for each update 11: Decrement by 0.5 dB for each update
3-2	PGA_RAMP_UP_SPEED	R/W	00	Digital Volume Normal Ramp Up Frequency These bits control the frequency of the digital volume updates when the volume is ramping up. 00: Update every 1 FS period 01: Update every 2 FS periods 10: Update every 4 FS periods 11: Directly restore the volume (Instant unmute)
1-0	PGA_RAMP_UP_STEP	R/W	11	Digital Volume Normal Ramp Up Step These bits control the step of the digital volume updates when the volume is ramping up. 00: Increment by 4 dB for each updat e 01: Increment by 2 dB for each update 10: Increment by 1 dB for each update 11: Increment by 0.5 dB for each update

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8.6.1.17 DIG_VOL_CTRL2 Register (Offset = 4Fh) [reset = 0x30]

DIG_VOL_CTRL2 is shown in Figure 30 and described in Table 22.

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Figure 30. DIG_VOL_CTRL2 Register

7	6	5	4	3	2	1	0
FAST_RAMP_DOWN_SPEED		FAST_RAMP_DOWN_STEP		RESERVED			
R/W		R/W		R/W			

Table 22. DIG_VOL_CTRL2 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	FAST_RAMP_DOWN_SPEED	R/W	00	Digital Volume Emergency Ramp Down Frequency These bits control the frequency of the digital volume updates when the volume is ramping down due to clock error or power outage, which usually needs faster ramp down compared to normal soft mute. 00: Update every 1 FS period 01: Update every 2 FS periods 10: Update every 4 FS periods 11: Directly set the volume to zero (Instant mute)
5-4	FAST_RAMP_DOWN_STEP	R/W	11	Digital Volume Emergency Ramp Down Step These bits control the step of the digital volume updates when the volume is ramping down due to clock error or power outage, which usually needs faster ramp down compared to normal soft mute. 00: Decrement by 4 dB for each update 01: Decrement by 2 dB for each update 10: Decrement by 1 dB for each update 11: Decrement by 0.5 dB for each update
3-0	RESERVED	R/W	0000	This bit is reserved

8.6.1.18 AUTO_MUTE_CTRL Register (Offset = 50h) [reset = 0x07]

AUTO_MUTE_CTRL is shown in Figure 31 and described in Table 23.

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Figure 31. AUTO_MUTE_CTRL Register

7	6	5	4	3	2	1	0
RESERVED					REG_AUTO_MUTE_CTRL		
R/W					R/W		

Table 23. AUTO_MUTE_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	00000	This bit is reserved
2-0	REG_AUTO_MUTE_CTRL	R/W	111	bit0: 0: Disable left channel auto mute 1: Enable left channel auto mute bit1: 0: Disable right channel auto mute 1: Enable right channel auto mute bit2: 0: Auto mute left channel and right channel independently. 1: Auto mute left and right channels only when both channels are about to be auto muted.

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8.6.1.19 AUTO_MUTE_TIME Register (Offset = 51h) [reset = 0x00]

AUTO_MUTE_TIME is shown in Figure 32 and described in Table 24.

Return to Summary Table.

Figure 32. AUTO_MUTE_TIME Register

7	6	5	4	3	2	1	0
RESERVED	AUTOMUTE_TIME_LEFT			RESERVED	AUTOMUTE_TIME_RIGHT		
R/W	R/W			R/W	R/W		

Table 24. AUTO_MUTE_TIME Register Field Descriptions

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6-4	AUTOMUTE_TIME_LEFT	R/W	000	Auto Mute Time for Left Channel These bits specify the length of consecutive zero samples at left channel before the channel can be auto muted. The times shown are for 96 kHz sampling rate and will scale with other rates. 000: 11.5 ms 001: 53 ms 010: 106.5 ms 011: 266.5 ms 100: 0.535 sec 101: 1.065 sec 110: 2.665 sec 111: 5.33 sec
3	RESERVED	R/W	0	This bit is reserved
2-0	AUTOMUTE_TIME_RIGHT	R/W	000	Auto Mute Time for Right Channel These bits specify the length of consecutive zero samples at right channel before the channel can be auto muted. The times shown are for 96 kHz sampling rate and will scale with other rates. 000: 11.5 ms 001: 53 ms 010: 106.5 ms 011: 266.5 ms 100: 0.535 sec 101: 1.065 sec 110: 2.665 sec 111: 5.33 sec

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8.6.1.20 ANA_CTRL Register (Offset = 53h) [reset = 0h]

ANA_CTRL is shown inFigure 33 and described in Table 25

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Figure 33. ANA_CTRL Register

7	6	5	4	3	2	1	0
AMUTE_DLY							
R/W							

Table 25. ANA_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6-5	Class D bandwidth control	R/W	00	00: 100kHz; 01: 80kHz; 10: 120kHz; 11:175kHz. With Fsw=384kHz, 100kHz bandwidth is selected for high audio performance. With Fsw=768kHz, 175kHz bandwidth should be selected for high audio performance.
4-1	RESERVED	R/W	0000	These bits are reserved
0	L and R PWM output phase control	R/W	0	0: out of phase; 1: in phase

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8.6.1.21 AGAIN Register (Offset = 54h) [reset = 0x00]

AGAIN is shown in Figure 34 and described in Table 26.

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Figure 34. AGAIN Register

7	6	5	4	3	2	1	0
RESERVED				ANA_GAIN			
R/W				R/W			

Table 26. AGAIN Register Field Descriptions

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	This bit is reserved
4-0	ANA_GAIN	R/W	00000	Analog Gain Control This bit controls the analog gain. 00000: 0 dB (29.5V peak voltage) 00001:-0.5db 11111: -15.5 dB

8.6.1.22 SPI_CLK Register (Offset = 55h) [reset = 0x00]

SPI_CLK is shown in Figure 35 and described in Table 27.

Return to Summary Table.

Figure 35. SPI_CLK Register

7	6	5	4	3	2	1	0
RESERVED				SPI_CLK_SEL			
R/W				R/W			

Table 27. SPI_CLK Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3-0	SPI_CLK_SEL	R/W	0000	00:1.25M 01:2.5M 10:5M 11:10M

8.6.1.23 EEPROM_CTRL0 Register (Offset = 56h) [reset = 0x00]

EEPROM_CTRL0 is shown in Figure 36 and described in Table 28.

Return to Summary Table.

Figure 36. EEPROM_CTRL0 Register

7	6	5	4	3	2	1	0
RESERVED		EEPROM_ADDR_24BITS_ENABLE	SPI_CLK_RATE		SPI_INV_POLAR	SPI_MST_LSB	LOAD_EEPROM_START
R/W		R/W	R/W		R/W	R/W	R/W

Table 28. EEPROM_CTRL0 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	RESERVED	R/W	00	This bit is reserved
5	EEPROM_ADDR_24BITS_ENABLE	R/W	0	enable 24 bits mode for EEPROM address
4-3	SPI_CLK_RATE	R/W	00	0: spi clock rate = 1.25MHz 1: spi clock rate = 2.5MHz 2: spi clock rate = 5MHz 3: spi clock rate = 10MHz
2	SPI_INV_POLAR	R/W	0	0: spi serial data change at post edge SCK 1: spi serial data change at neg edge SCK
1	SPI_MST_LSB	R/W	0	0: msb first 1: lsb first
0	LOAD_EEPROM_START	R/W	0	0: dsp coefficients read from host 1: dsp coefficients read from EEPROM

8.6.1.24 EEPROM_RD_CMD Register (Offset = 57h) [reset = 0x03]

EEPROM_RD_CMD is shown in Figure 37 and described in Table 29.

Return to Summary Table.

Figure 37. EEPROM_RD_CMD Register

7	6	5	4	3	2	1	0
EEPROM_RD_CMD							
R/W-00000011							

Table 29. EEPROM_RD_CMD Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	EEPROM_RD_CMD	R/W	00000011	EEPROM read command

8.6.1.25 EEPROM_ADDR_START0 Register (Offset = 58h) [reset = 0x00]

EEPROM_ADDR_START0 is shown in Figure 38 and described in Table 30.

Return to Summary Table.

Figure 38. EEPROM_ADDR_START0 Register

7	6	5	4	3	2	1	0
EEPROM_ADDR_START_HIGH							
R/W							

Table 30. EEPROM_ADDR_START0 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	EEPROM_ADDR_START_HIGH	R/W	00000000	8 msb of EEPROM read starting address for coefficient

8.6.1.26 EEPROM_ADDR_START1 Register (Offset = 59h) [reset = 0x00]

EEPROM_ADDR_START1 is shown in Figure 39 and described in Table 31.

Return to Summary Table.

Figure 39. EEPROM_ADDR_START1 Register

7	6	5	4	3	2	1	0
EEPROM_ADDR_START_MIDDLE							
R/W							

Table 31. EEPROM_ADDR_START1 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	EEPROM_ADDR_START_MIDDLE	R/W	00000000	8 middle of EEPROM read starting address for coefficients

8.6.1.27 EEPROM_ADDR_START2 Register (Offset = 5Ah) [reset = 0h]

EEPROM_ADDR_START2 is shown in Figure 40 and described in Table 32.

Return to Summary Table.

Figure 40. EEPROM_ADDR_START2 Register

7	6	5	4	3	2	1	0
EEPROM_ADDR_START_LOW							
R/W							

Table 32. EEPROM_ADDR_START2 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	EEPROM_ADDR_START_LOW	R/W	00000000	8 lsb of EEPROM read starting address for coefficients

8.6.1.28 EEPROM_BOOT_STATUS Register (Offset = 5Bh) [reset = 0x00]

EEPROM_BOOT_STATUS is shown in Figure 41 and described in Table 33.

Return to Summary Table.

Figure 41. EEPROM_BOOT_STATUS Register

7	6	5	4	3	2	1	0
RESERVED						LOAD_EEPROM_CRC_ERROR	LOAD_EEPROM_DONE
R						R	R

Table 33. EEPROM_BOOT_STATUS Register Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	000000	This bit is reserved
1	LOAD_EEPROM_CRC_ERROR	R	0	0: CRC pass for EEPROM boot load 1: CRC don't passs for EEPROM boot load.
0	LOAD_EEPROM_DONE	R	0	Indicate that the EEPROM boot load has been finished.

8.6.1.29 BQ_WR_CTRL1 Register (Offset = 5Ch) [reset = 0x000]

BQ_WR_CTRL1 is shown in Figure 42 and described in Table 34.

Return to Summary Table.

Figure 42. BQ_WR_CTRL1 Register

7	6	5	4	3	2	1	0
RESERVED							BQ_WR_FIRST_COEF
R/W							R/W

Table 34. BQ_WR_CTRL1 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000000	This bit is reserved
0	BQ_WR_FIRST_COEF	R/W	0	Indicate the first coefficient of a BQ is starting to write.

8.6.1.30 ADC_RPT Register (Offset = 5Eh) [reset = 0h]

ADC_RPT is shown in Figure 43 and described in Table 35.

Return to Summary Table.

Figure 43. ADC_RPT Register

7	6	5	4	3	2	1	0
ADC_DATA_OUT							
R							

Table 35. ADC_RPT Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	ADC_DATA_OUT	R	00000000	adc data out

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8.6.1.31 GPIO_CTRL Register (Offset = 60h) [reset = 0x00]

GPIO_CTRL is shown in Figure 44 and described in Table 36.

Return to Summary Table.

Figure 44. GPIO_CTRL Register

7	6	5	4	3	2	1	0
RESERVED					GPIO2_OE	GPIO1_OE	GPIO0_OE
R/W					R/W	R/W	R/W

Table 36. GPIO_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	0000	This bit is reserved
2	GPIO2_OE	R/W	0	GPIO2 Output Enable This bit sets the direction of the GPIO2 pin 0: GPIO2 is input 1: GPIO2 is output
1	GPIO1_OE	R/W	0	GPIO1 Output Enable This bit sets the direction of the GPIO1 pin 0: GPIO1 is input 1: GPIO1 is output
0	GPIO0_OE	R/W	0	GPIO0 Output Enable This bit sets the direction of the GPIO0 pin 0: GPIO0 is input 1: GPIO0 is output

8.6.1.32 GPIO0_SEL Register (Offset = 61h) [reset = 0x00]

GPIO0_SEL is shown in Figure 45 and described in Table 37.

Return to Summary Table.

Figure 45. GPIO0_SEL Register

7	6	5	4	3	2	1	0
RESERVED				GPIO0_SEL			
R/W				R/W			

Table 37. GPIO0_SEL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3-0	GPIO0_SEL	R/W	0000	0000: off (low) 0001: Reserved 0010: Register GPIO0 output 0011: Auto mute flag (asserted when both L and R channels are auto muted) 0100: Auto mute flag for left channel 0101: Auto mute flag for right channel 0110: Clock invalid flag (clock error or clock missing) 0111: Reserved 1000: GPIO0 as WARNZ output 1001: Serial audio interface data output (SDOUT) 1011: GPIO0 as FAULTZ output 1100: GPIO0 as SPI CLK 1101: GPIO0 as SPI_MOSI 1110: Reserved 1111: Reserved

8.6.1.33 GPIO1_SEL Register (Offset = 62h) [reset = 0x00]

GPIO1_SEL is shown in Figure 46 and described in Table 38.

Return to Summary Table.

Figure 46. GPIO1_SEL Register

7	6	5	4	3	2	1	0
RESERVED				GPIO1_SEL			
R/W				R/W			

Table 38. GPIO1_SEL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3-0	GPIO1_SEL	R/W	0000	0000: off (low) 0001: Reserved 0010: Register GPIO1 output 0011: Auto mute flag (asserted when both L and R channels are auto muted) 0100: Auto mute flag for left channel 0101: Auto mute flag for right channel 0110: Clock invalid flag (clock error or clock missing) 0111: Reserved 1000: GPIO1 as WARNZ output 1001: Serial audio interface data output (SDOUT) 1011: GPIO1 as FAULTZ output 1100: GPIO1 as SPI CLK 1101: GPIO1 as SPI_MOSI 1110: Reserved 1111: Reserved

ADVANCE INFORMATION

8.6.1.34 GPIO2_SEL Register (Offset = 63h) [reset = 0x00]

GPIO2_SEL is shown in Figure 47 and described in Table 39.

Return to Summary Table.

Figure 47. GPIO2_SEL Register

7	6	5	4	3	2	1	0
RESERVED				GPIO2_SEL			
R/W				R/W			

Table 39. GPIO2_SEL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3-0	GPIO2_SEL	R/W	0000	0000: off (low) 0001: Reserved 0010: Register GPIO2 output 0011: Auto mute flag (asserted when both L and R channels are auto muted) 0100: Auto mute flag for left channel 0101: Auto mute flag for right channel 0110: Clock invalid flag (clock error or clock missing) 0111: Reserved 1000: GPIO2 as WARNZ output 1001: Serial audio interface data output (SDOUT) 1011: GPIO2 as FAULTZ output 1100: GPIO2 as SPI CLK 1101: GPIO2 as SPI_MOSI 1110: Reserved 1111: Reserved

8.6.1.35 GPIO_INPUT_SEL Register (Offset = 64h) [reset = 0x00]

GPIO_INPUT_SEL is shown in Figure 48 and described in Table 40.

Return to Summary Table.

Figure 48. GPIO_INPUT_SEL Register

7	6	5	4	3	2	1	0
GPIO_SPI_MISO_SEL		GPIO_PHASE_SYNC_SEL		GPIO_RESETZ_SEL		GPIO_MUTEZ_SEL	
R/W		R/W		R/W		R/W	

Table 40. GPIO_INPUT_SEL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	GPIO_SPI_MISO_SEL	R/W	00	00: N/A 01: GPIO0 10: GPIO1 11: GPIO2
5-4	GPIO_PHASE_SYNC_SEL	R/W	00	00: N/A 01: GPIO0 10: GPIO1 11: GPIO2
3-2	GPIO_RESETZ_SEL	R/W	00	00: N/A 01: GPIO0 10: GPIO1 11: GPIO2 can not be reset by GPIO reset
1-0	GPIO_MUTEZ_SEL	R/W	00	00: N/A 01: GPIO0 10: GPIO1 11: GPIO2

ADVANCE INFORMATION

8.6.1.36 GPIO_OUT Register (Offset = 65h) [reset = 0x00]

GPIO_OUT is shown in Figure 49 and described in Table 41.

Return to Summary Table.

Figure 49. GPIO_OUT Register

7	6	5	4	3	2	1	0
RESERVED					GPIO_OUT		
R/W					R/W		

Table 41. GPIO_OUT Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	00000	This bit is reserved
2-0	GPIO_OUT	R/W	000	bit0: GPIO0 output bit1: GPIO1 output bit2: GPIO2 output

8.6.1.37 GPIO_OUT_INV Register (Offset = 66h) [reset = 0x00]

GPIO_OUT_INV is shown in Figure 50 and described in Table 42.

Return to Summary Table.

Figure 50. GPIO_OUT_INV Register

7	6	5	4	3	2	1	0
RESERVED					GPIO_OUT		
R/W					R/W		

Table 42. GPIO_OUT_INV Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	00000	This bit is reserved
2-0	GPIO_OUT	R/W	000	bit0: GPIO0 output invert bit1: GPIO1 output invert bit2: GPIO2 output invert

8.6.1.38 DIE_ID Register (Offset = 67h) [reset = 95h]

DIE_ID is shown in Figure 51 and described in Table 43.

Return to Summary Table.

Figure 51. DIE_ID Register

7	6	5	4	3	2	1	0
DIE_ID							
R							

Table 43. DIE_ID Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	DIE_ID	R	10010101	DIE ID

ADVANCE INFORMATION

8.6.1.39 POWER_STATE Register (Offset = 68h) [reset = 0x00]

POWER_STATE is shown in Figure 52 and described in Table 44.

Return to Summary Table.

Figure 52. POWER_STATE Register

7	6	5	4	3	2	1	0
STATE_RPT							
R							

Table 44. POWER_STATE Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	STATE_RPT	R	00000000	0: Deep sleep 1: Seep 2: HIZ 3: Play others: reserved

8.6.1.40 AUTOMUTE_STATE Register (Offset = 69h) [reset = 0x00]

AUTOMUTE_STATE is shown in Figure 53 and described in Table 45.

Return to Summary Table.

Figure 53. AUTOMUTE_STATE Register

7	6	5	4	3	2	1	0
RESERVED						ZERO_RIGHT_MON	ZERO_LEFT_MON
R						R	R

Table 45. AUTOMUTE_STATE Register Field Descriptions

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	000000	This bit is reserved
1	ZERO_RIGHT_MON	R	0	This bit indicates the auto mute status for right channel. 0: Not auto muted 1: Auto muted
0	ZERO_LEFT_MON	R	0	This bit indicates the auto mute status for left channel. 0: Not auto muted 1: Auto muted

8.6.1.41 PHASE_CTRL Register (Offset = 6Ah) [reset = 0]

PHASE_CTRL is shown in Figure 54 and described in Table 46.

Return to Summary Table.

Figure 54. PHASE_CTRL Register

7	6	5	4	3	2	1	0
RESERVED				RAMP_PHASE_SEL		PHASE_SYNC_SEL	PHASE_SYNC_EN
R/W				R/W		R/W	R/W

Table 46. PHASE_CTRL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3-2	RAMP_PHASE_SEL	R/W	00	select ramp clock phase when multi devices integrated in one system to reduce EMI and peak supply peak current, it is recomended set all devices the same RAMP frequency and same spread spectrum. it must be set before driving device into PLAY mode if this feature is needed. 2'b00: phase 0 2'b01: phase 1 2'b10: phase 2 2'b11: phase 3 all of above have a 45 degree of phase shift
1	PHASE_SYNC_SEL	R/W	0	ramp phase sync sel, 0: is gpio sync; 1: intenal sync
0	PHASE_SYNC_EN	R/W	0	ramp phase sync enable

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8.6.1.42 RAMP_SS_CTRL0 Register (Offset = 6Bh) [reset = 0x00]

RAMP_SS_CTRL0 is shown in Figure 55 and described in Table 47.

Return to Summary Table.

Figure 55. SS_CTRL0 Register

7	6	5	4	3	2	1	0
RESERVED	RESERVED	SS_PRE_DIV_SEL	SS_MANUAL_MODE	RESERVED		SS_RDM_EN	SS_TRI_EN
R/W	R/W	R/W	R/W	R/W		R/W	R/W

Table 47. RAMP_SS_CTRL0 Register Field Descriptions

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6	RESERVED	R/W	0	This bit is reserved
5	SS_PRE_DIV_SEL	R/W	0	select pll clock divide 2 as source clock in manual mode
4	SS_MANUAL_MODE	R/W	0	set ramp ss controller to manual mode
3-2	RESERVED	R/W	00	This bit is reserved
1	SS_RDM_EN	R/W	0	random SS enable
0	SS_TRI_EN	R/W	0	triangle SS enable

8.6.1.43 SS_CTRL1 Register (Offset = 6Ch) [reset = 0x00]

SS_CTRL1 is shown in Figure 56 and described in Table 48.

Return to Summary Table.

Figure 56. SS_CTRL1 Register

7	6	5	4	3	2	1	0
RESERVED	SS_RDM_CTRL			SS_TRI_CTRL			
R/W	R/W			R/W			

Table 48. SS_CTRL1 Register Field Descriptions

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6-4	SS_RDM_CTRL	R/W	000	Add Dither
3-0	SS_TRI_CTRL	R/W	0000	triangle SS frequency and range control

ADVANCE INFORMATION

8.6.1.44 SS_CTRL2 Register (Offset = 6Dh) [reset = 0xA0]

SS_CTRL2 is shown in Figure 57 and described in Table 49.

Return to Summary Table.

Figure 57. SS_CTRL2 Register

7	6	5	4	3	2	1	0
TM_FREQ_CTRL							
R/W							

Table 49. SS_CTRL2 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-0	TM_FREQ_CTRL	R/W	10100000	control ramp frequency in manual mode, F=61440000/N

8.6.1.45 SS_CTRL3 Register (Offset = 6Eh) [reset = 0x11]

SS_CTRL3 is shown in Figure 58 and described in Table 50.

Return to Summary Table.

Figure 58. SS_CTRL3 Register

7	6	5	4	3	2	1	0
TM_DSTEP_CTRL				TM_USTEP_CTRL			
R/W				R/W			

Table 50. SS_CTRL3 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	SS_TM_DSTEP_CTRL	R/W	0001	control triangel mode spread spectrum fall step in ramp ss manual mode
3-0	SS_TM_USTEP_CTRL	R/W	0001	control triangle mode spread spectrum rise step in ramp ss manual mode

8.6.1.46 SS_CTRL4 Register (Offset = 6Fh) [reset = 0x24]

SS_CTRL4 is shown in Figure 59 and described in Table 51.

Return to Summary Table.

Figure 59. SS_CTRL4 Register

7	6	5	4	3	2	1	0
RESERVED	TM_AMP_CTRL		SS_TM_PERIOD_BOUNDRY				
R/W	R/W		R/W				

Table 51. SS_CTRL4 Register Field Descriptions

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6-5	TM_AMP_CTRL	R/W	01	control ramp amp ctrl in ramp ss manual model
4-0	SS_TM_PERIOD_BOUNDRY	R/W	00100	control triangle mode spread spectrum boundary in ramp ss manual mode

ADVANCE INFORMATION

8.6.1.47 CHAN_FAULT Register (Offset = 70h) [reset = 0x00]

CHAN_FAULT is shown in Figure 60 and described in Table 52.

Return to Summary Table.

Figure 60. CHAN_FAULT Register

7	6	5	4	3	2	1	0
RESERVED				CH1_DC_1	CH2_DC_1	CH1_OC_I	CH2_OC_I
R				R	R	R	R

Table 52. CHAN_FAULT Register Field Descriptions

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0000	This bit is reserved
3	CH1_DC_1	R	0	left channel DC fault
2	CH2_DC_1	R	0	right channel DC fault
1	CH1_OC_I	R	0	left channel over current fault
0	CH2_OC_I	R	0	right channel over current fault

8.6.1.48 GLOBAL_FAULT1 Register (Offset = 71h) [reset = 0h]

GLOBAL_FAULT1 is shown in Figure 61 and described in Table 53.

Return to Summary Table.

Figure 61. GLOBAL_FAULT1 Register

7	6	5	4	3	2	1	0
OTP_CRC_ERROR	BQ_WR_ERROR	LOAD_EEPROM_ERROR	DVDD_UV_I	DVDD_OV_I	CLK_FAULT_I	PVDD_OV_I	PVDD_UV_I
R	R	R	R	R	R	R	R

Table 53. GLOBAL_FAULT1 Register Field Descriptions

Bit	Field	Type	Reset	Description
7	OTP_CRC_ERROR	R	0	Indicate OTP CRC check error.
6	BQ_WR_ERROR	R	0	the recent BQ is written failed
5	LOAD_EEPROM_ERROR	R	0	0: EEPROM boot load was done successfully 1: EEPROM boot load was done unsuccessfully
4	DVDD_UV_I	R	0	DVDD UV fault
3	DVDD_OV_I	R	0	DVDD OV fault
2	CLK_FAULT_I	R	0	clock fault
1	PVDD_OV_I	R	0	PVDD OV fault
0	PVDD_UV_I	R	0	PVDD UV fault

ADVANCE INFORMATION

8.6.1.49 GLOBAL_FAULT2 Register (Offset = 72h) [reset = 0h]

GLOBAL_FAULT2 is shown in Figure 62 and described in Table 54.

Return to Summary Table.

Figure 62. GLOBAL_FAULT2 Register

7	6	5	4	3	2	1	0
RESERVED					CBC_FAULT_CH2_I	CBC_FAULT_CH1_I	OTSD_I
R					R	R	R

Table 54. GLOBAL_FAULT2 Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R	0000	This bit is reserved
2	CBC_FAULT_CH2_I	R	0	right channel cycle by cycle over current fault
1	CBC_FAULT_CH1_I	R	0	left channel cycle by cycle over current fault
0	OTSD_I	R	0	over temperature shut down fault

8.6.1.50 WARNING Register (Offset = 73h) [reset = 0x00]

WARNING is shown in Figure 63 and described in Table 55.

Return to Summary Table.

Figure 63. WARNING Register

7	6	5	4	3	2	1	0
RESERVED		CBCW_CH1_I	CBCW_CH2_I	OTW_LEVEL4_I	OTW_LEVEL3_I	OTW_LEVEL2_I	OTW_LEVEL1_I
R		R	R	R	R	R	R

Table 55. WARNING Register Field Descriptions

Bit	Field	Type	Reset	Description
7-6	RESERVED	R	0	This bit is reserved
5	CBCW_CH1_I	R	0	left channel cycle by cycle over current warning
4	CBCW_CH2_I	R	0	right channel cycle by cycle over current warning
3	OTW_LEVEL4_I	R	0	over temperature warning leve4, 146C
2	OTW_LEVEL3_I	R	0	over temperature warning leve3, 134C
1	OTW_LEVEL2_I	R	0	over temperature warning leve2, 122C
0	OTW_LEVEL1_I	R	0	over temperature warning leve1, 112C

ADVANCE INFORMATION

8.6.1.51 PIN_CONTROL1 Register (Offset = 74h) [reset = 0x00]

PIN_CONTROL1 is shown in Figure 64 and described in Table 56.

Return to Summary Table.

Figure 64. PIN_CONTROL1 Register

7	6	5	4	3	2	1	0
MASK_OTSD	MASK_DVDD_UV	MASK_DVDD_OV	MASK_CLK_FAULT	RESERVED	MASK_PVDD_UV	MASK_DC	MASK_OC
R/W	R/W	R/W	R/W	R	R/W	R/W	R/W

Table 56. PIN_CONTROL1 Register Field Descriptions

Bit	Field	Type	Reset	Description
7	MASK_OTSD	R/W	0	mask OTSD fault report
6	MASK_DVDD_UV	R/W	0	mask DVDD UV fault report
5	MASK_DVDD_OV	R/W	0	mask DVDD OV fault report
4	MASK_CLK_FAULT	R/W	0	mask clock fault report
3	RESERVED	R	0	
2	MASK_PVDD_UV	R/W	0	mask PVDD UV fault report mask PVDD OV fault report
1	MASK_DC	R/W	0	mask DC fault report
0	MASK_OC	R/W	0	mask OC fault report

8.6.1.52 PIN_CONTROL2 Register (Offset = 75h) [reset = 0xF8]

PIN_CONTROL2 is shown in Figure 65 and described in Table 57.

Return to Summary Table.

Figure 65. PIN_CONTROL2 Register

7	6	5	4	3	2	1	0
CBC_FAULT_LATCH_EN	CBC_WARN_LATCH_EN	CLKFLT_LATCH_EN	OTSD_LATCH_EN	OTW_LATCH_EN	MASK_OTW	MASK_CBCW	MASK_CBC_FAULT
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

Table 57. PIN_CONTROL2 Register Field Descriptions

Bit	Field	Type	Reset	Description
7	CBC_FAULT_LATCH_EN	R/W	1	enable CBC fault latch
6	CBC_WARN_LATCH_EN	R/W	1	enable CBC warning latch
5	CLKFLT_LATCH_EN	R/W	1	enable clock fault latch
4	OTSD_LATCH_EN	R/W	1	enable OTSD fault latch
3	OTW_LATCH_EN	R/W	1	enable OT warning latch
2	MASK_OTW	R/W	0	mask OT warning report
1	MASK_CBCW	R/W	0	mask CBC warning report
0	MASK_CBC_FAULT	R/W	0	mask CBC fault report

ADVANCE INFORMATION

8.6.1.53 MISC_CONTROL Register (Offset = 76h) [reset = 0x00]

MISC_CONTROL is shown in Figure 66 and described in Table 58.

Return to Summary Table.

Figure 66. MISC_CONTROL Register

7	6	5	4	3	2	1	0
DET_STATUS_LATCH	RESERVED		OTSD_AUTO_REC_EN	RESERVED			
R/W	R/W		R/W	R/W			

Table 58. MISC_CONTROL Register Field Descriptions

Bit	Field	Type	Reset	Description
7	DET_STATUS_LATCH	R/W	0	1:latch clock detection status 0:don't latch clock detection status
6-5	RESERVED	R/W	00	This bit is reserved
4	OTSD_AUTO_REC_EN	R/W	0	OTSD auto recovery enable
3-0	RESERVED	R/W	0000	This bit is reserved

8.6.1.54 CBC_CONTROL Register (Offset = 77h) [reset = 0x00]

CBC_CONTROL is shown in Figure 67 and described in Table 59.

Return to Summary Table.

Figure 67. CBC_CONTROL Register

7	6	5	4	3	2	1	0
RESERVED					CBC_EN	CBC_WARN_EN	CBC_FAULT_EN
R/W					R/W	R/W	R/W

Table 59. CBC_CONTROL Register Field Descriptions

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	00000	This bit is reserved
2	CBC_EN	R/W	0	enable CBC function
1	CBC_WARN_EN	R/W	0	enable CBC warning
0	CBC_FAULT_EN	R/W	0	enable CBC fault

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8.6.1.55 FAULT_CLEAR Register (Offset = 78h) [reset = 0x00]

FAULT_CLEAR is shown in Figure 68 and described in Table 60.

Return to Summary Table.

Figure 68. FAULT_CLEAR Register

7	6	5	4	3	2	1	0
ANALOG_FAULT_CLEAR	RESERVED						
W	R/W						

Table 60. FAULT_CLEAR Register Field Descriptions

Bit	Field	Type	Reset	Description
7	ANALOG_FAULT_CLEAR	W	0	WRITE CLEAR BIT once write this bit to 1, device will clear analog fault
6-0	RESERVED	R/W	0000000	This bit is reserved

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

This section details the information required to configure the device for several popular configurations and provides guidance on integrating the TAS5825M device into the larger system.

9.1.1 Bootstrap Capacitors

The output stage of the TAS5825M uses a high-side NMOS driver, rather than a PMOS driver. To generate the gate driver voltage for the high-side NMOS, a bootstrap capacitor for each output terminal acts as a floating power supply for the switching cycle. Use 0.22-µF capacitors to connect the appropriate output pin (OUT_X) to the bootstrap pin (BST_X). For example, connect a 0.22-µF capacitor between OUT_A and BST_A for bootstrapping the A channel. Similarly, connect another 0.22-µF capacitor between the OUT_B and BST_B pins for the B channel inverting output.

9.1.2 Power Supply Decoupling

To ensure high efficiency, low THD, and high PSRR, proper power supply decoupling is necessary. Noise transients on the power supply lines are short duration voltage spikes. These spikes can contain frequency components that extend into the hundreds of megahertz. The power supply input must be decoupled with some good quality, low ESL, Low ESR capacitors larger than 22 µF. These capacitors bypasses low frequency noise to the ground plane. For high frequency decoupling, place 1-µF or 0.1-µF capacitors as close as possible to the PVDD pins of the device.

9.1.3 Output EMI Filtering

The TAS5825M device is often used with a low-pass filter, which is used to filter out the carrier frequency of the PWM modulated output. This filter is frequently referred to as the L-C Filter, due to the presence of an inductive element L and a capacitive element C to make up the 2-pole filter.

The L-C filter removes the carrier frequency, reducing electromagnetic emissions and smoothing the current waveform which is drawn from the power supply. The presence and size of the L-C filter is determined by several system level constraints. In some low-power use cases that have no other circuits which are sensitive to EMI, a simple ferrite bead or a ferrite bead plus a capacitor can replace the tradition large inductor and capacitor that are commonly used. In other high-power applications, large toroid inductors are required for maximum power and film capacitors can be used due to audio characteristics. Refer to the application report Class-D LC Filter Design (SLOA119) for a detailed description on the proper component selection and design of an L-C filter based upon the desired load and response.

9.2 Typical Applications

9.2.1 2.0 (Stereo BTL) System

In the 2.0 system, two channels are presented to the amplifier via the digital input signal. These two channels are amplified and then sent to two separate speakers. In some cases, the amplified signal is further separated based upon frequency by a passive crossover network after the L-C filter. Even so, the application is considered 2.0.

Most commonly, the two channels are a pair of signals called a stereo pair, with one channel containing the audio for the left channel and the other channel containing the audio for the right channel. While certainly the two channels can contain any two audio channels, such as two surround channels of a multi-channel speaker system, the most popular occurrence in two channels systems is a stereo pair.

Figure 69 shows the 2.0 (Stereo BTL) system application.

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Typical Applications (continued)

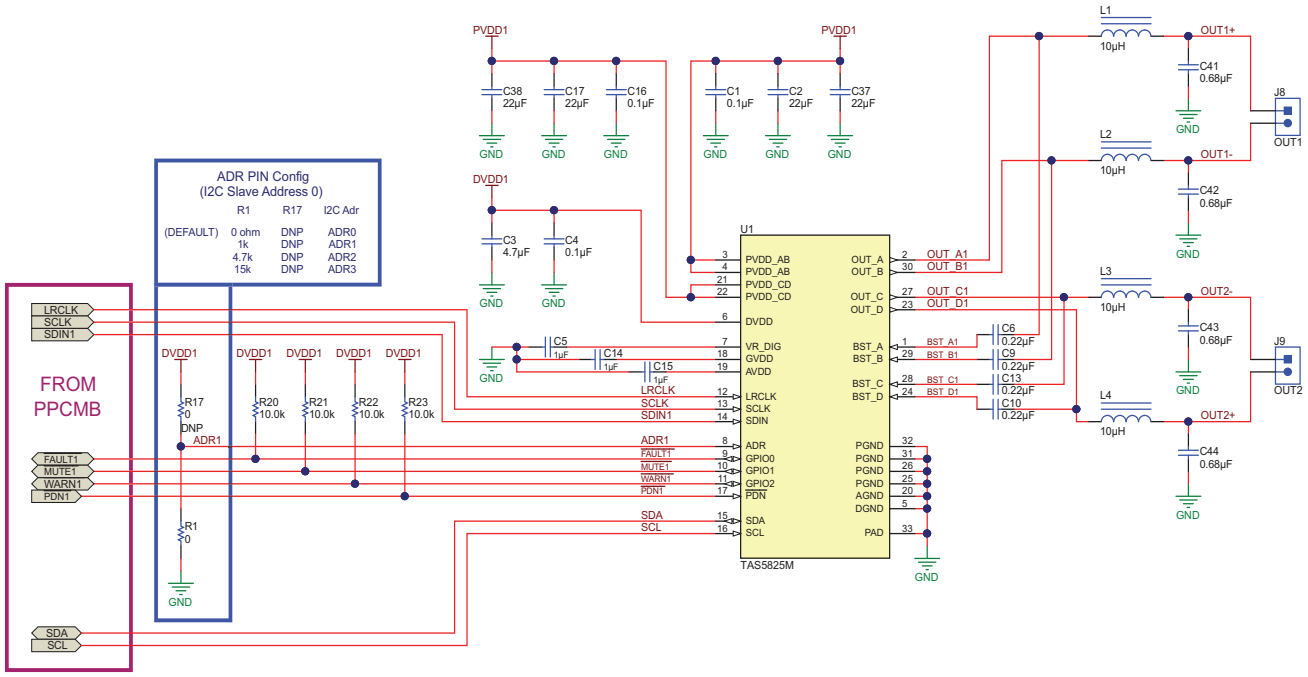

Figure 69. 2.0 (Stereo BTL) System Application Schematic

ADVANCE INFORMATION

Typical Applications (continued)

9.2.2 Design Requirements

- Power supplies:
  - 3.3-V supply
  - 5-V to 24-V supply
- Communication: host processor serving as I^2C compliant master
- External memory (such as EEPROM and FLASH) used for coefficients.

The requirements for the supporting components for the TAS5825M device in a Stereo 2.0 (BTL) system is provide in Table 61.

Table 61. Supporting Component Requirements for Stereo 2.0 (BTL) Systems

REFERENCE DESIGNATOR	VALUE	SIZE	DETAILED DESCRIPTION
C1, C16	0.1 µF	0402	CAP, CERM, 0.1 µF, 50 V, ±10%, X7R, 0402
C2, C17, C37, C38	22 µF	0805	CAP, CERM, 22 µF, 35 V, ±20%, JB, 0805
C3	4.7 µF	0603	CAP, CERM, 4.7 µF, 10 V, ±10%, X5R, 0603
C4	0.1 µF	0603	CAP, CERM, 0.1 µF, 16 V, ±10%, X7R, 0603
C5, C14, C15	1 µF	0603	CAP, CERM, 1 µF, 16 V, ±10%, X5R, 0603
C6, C9, C10, C13	0.22 µF	0603	CAP, CERM, 0.22 µF, 50 V, ±10%, X7R, 0603
C41, C42, C43, C44	0.68 µF	0805	CAP, CERM, 0.68 µF, 50 V, ±10%, X7R, 0805
L1, L2, L3, L4	10 µH		Inductor, Shielded, Ferrite, 10 µH, 4.4 A, 0.0304 Ω, SMD 1274AS-H-100M=P3
R1,R17(DNP)	0 Ω	0402	RES, 0, 5%, 0.063 W, 0402
R20, R21, R22, R23	10 kΩ	0402	RES, 10.0 k, 1%, 0.063 W, 0402

9.2.3 Detailed Design procedures

9.2.3.1 Step One: Hardware Integration

- Using the Typical Application Schematic as a guide, integrate the hardware into the system schematic.
- Following the recommended component placement, board layout, and routing given in the example layout above, integrate the device and its supporting components into the system PCB file.
  - The most critical sections of the circuit are the power supply inputs, the amplifier output signals, and the high-frequency signals, all of which go to the serial audio port. Constructing these signals to ensure they are given precedent as design trade-offs are made is recommended.
  - For questions and support go to the E2E forums (e2e.ti.com). If deviating from the recommended layout is necessary, go to the E2E forum to request a layout review.

9.2.3.2 Step Two: Hardware Integration

Using the TAS5825MEVM evaluation module and the PPC3 app to configure the desired device settings.

9.2.3.3 Step Three: Software Integration

- Using the End System Integration feature of the PPC3 app to generate a baseline configuration file.
- Generate additional configuration files based upon operating modes of the end-equipment and integrate static configuration information into initialization files.
- Integrate dynamic controls (such as volume controls, mute commands, and mode-based EQ curves) into the main system program.

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9.2.4 2.1 (Stereo BTL + External Mono Amplifier) Systems

To increase the low-frequency output capabilities of an audio system, a single subwoofer can be added to the system. Because the spatial clues for audio are predominately higher frequency than that reproduced by the subwoofer, often a signal subwoofer can be used to reproduce the low frequency content of several other channels in the system. This is frequently referred to as a dot one system. A stereo system with a subwoofer is referred to as a 2.1 (two-dot-one), a 3 channel system with subwoofer is referred to as a 3.1 (three-do-one), a popular surround system with five speakers and one subwoofer is referred to as a 5.1, and so on

9.2.5 Advanced 2.1 System (Two TAS5825M Devices)

In higher performance systems, the subwoofer output can be enhanced using digital audio processing as was done in the high-frequency channels. To accomplish this, two TAS5825M devices are used - one for the high frequency left and right speakers and one for the mono subwoofer speaker. In this system, the audio signal can be sent from the TAS5825M device through the SDOUT pin. Alternatively, the subwoofer amplifier can accept the same digital input as the stereo (Shown in Figure 69), which might come from a central systems processor. Figure 70 shows in the Sub-woofer (PBTL) Application Schematic.

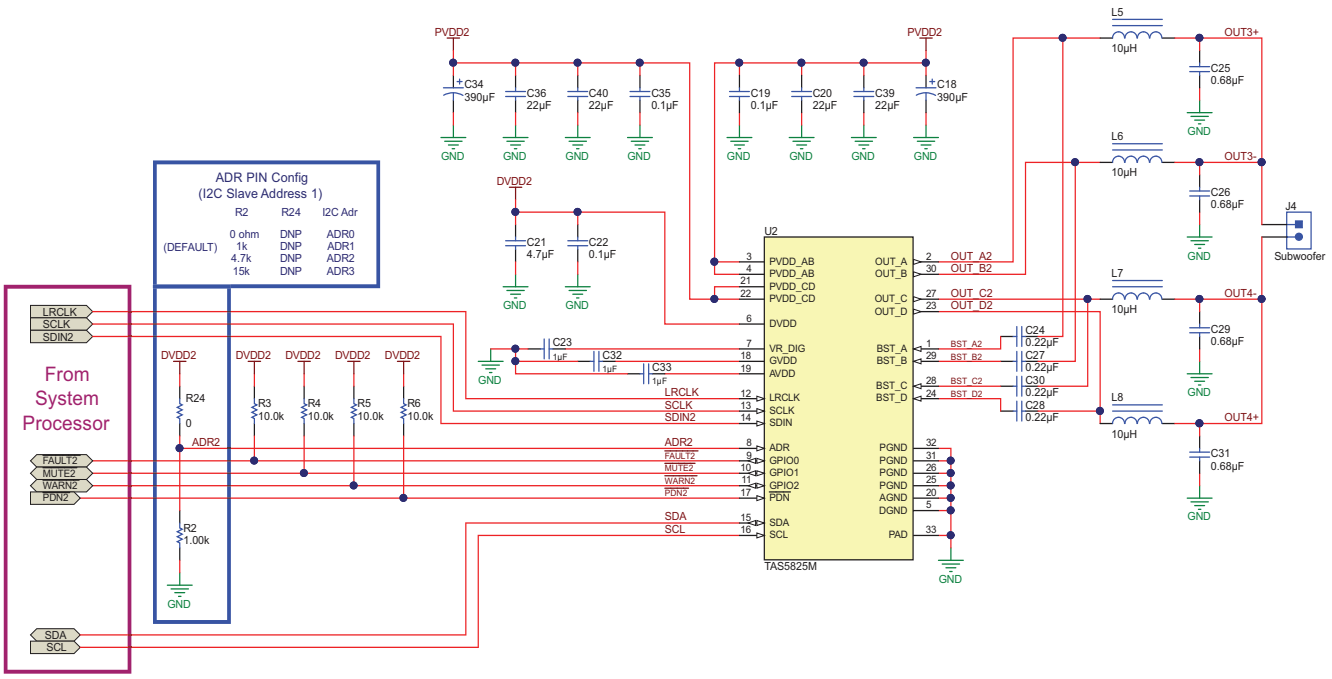

Figure 70. Sub-woofer (PBTL) Application Schematic

10 Power Supply Recommendations

The TAS5825M device requires two power supplies for proper operation. A high-voltage supply calls PVDD is required to power the output stage of the speaker amplifier and its associated circuitry. Additionally, one low-voltage power supply which is calls DVDD is required to power the various low-power portions of the device. The allowable voltage range for both PVDD and DVDD supply are listed in the *Recommended Operating Conditions* table. The two power supplies do not have a required powerup sequence. The power supplies can be powered on in any order. TI recommends waiting 100 ms to 240 ms for the DVDD power supplies to stabilize before starting I^2C communication and providing stable I^2S clock before enabling the device outputs.

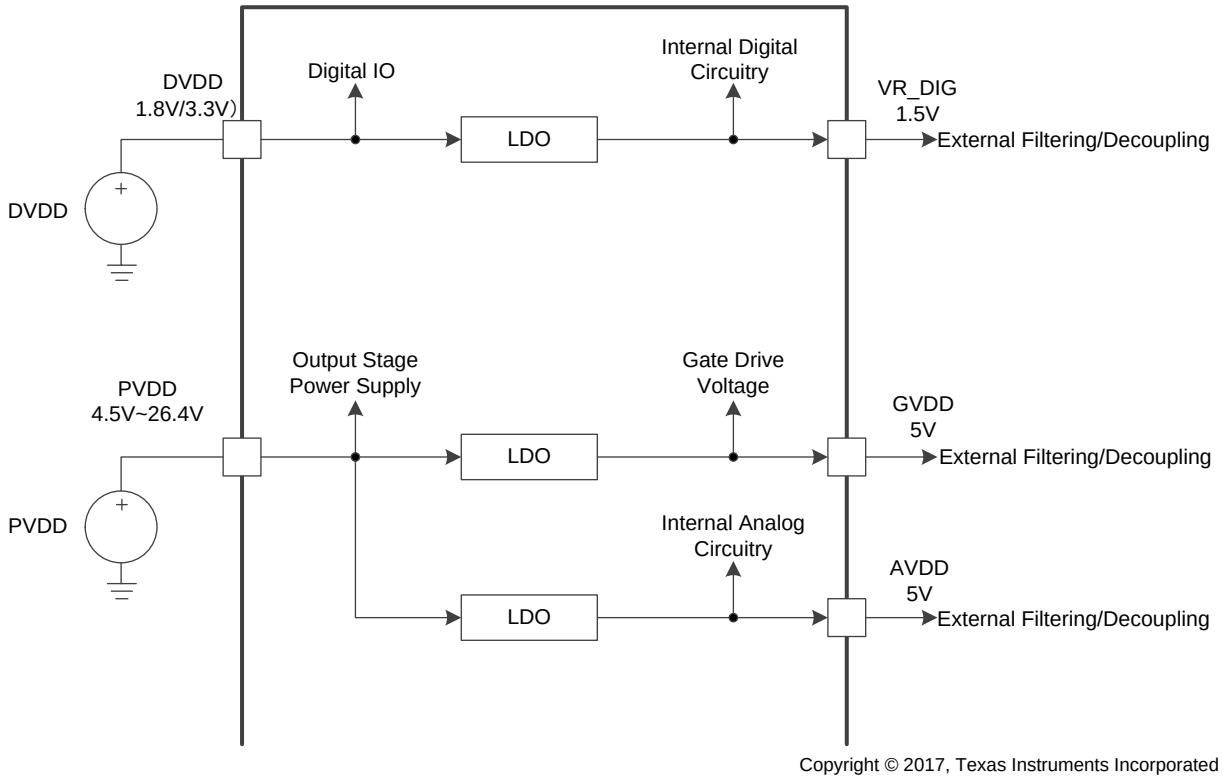

Figure 71. Power Supply Function Block Diagram

10.1 DVDD Supply

The DVDD supply that is required from the system is used to power several portions of the device. As shown in Figure 71, it provides power to the DVDD pin. Proper connection, routing and decoupling techniques are highlighted in the *Application and Implementation* section and the *Layout Example* section and must be followed as closely as possible for proper operation and performance.

Some portions of the device also require a separate power supply that is a lower voltage than the DVDD supply. To simplify the power supply requirements for the system, the TAS5825M device includes an integrated low dropout (LDO) linear regulator to create this supply. This linear regulator is internally connected to the DVDD supply and its output is presented on the DVDD_REG pin, providing a connection point for an external bypass capacitor. It is important to note that the linear regulator integrated in the device has only been designed to support the current requirements of the internal circuitry, and should not be used to power any additional external circuitry. Additional loading on this pin could cause the voltage to sag, negatively affecting the performance and operation of the device.

ADVANCE INFORMATION

10.2 PVDD Supply

The output stage of the speaker amplifier drives the load using the PVDD supply. This is the power supply which provides the drive current to the load during playback. Proper connection, routing, and decoupling techniques are highlighted in the TAS5825MEVM and must be followed as closely as possible for proper operation and performance. Due to the high-voltage switching of the output stage, it is particularly important to properly decouple the output power stages in the manner described in the TAS5825M device *Application and Implementation*. Lack of proper decoupling, like that shown in the *Application and Implementation*, results in voltage spikes which can damage the device.

A separate power supply is required to drive the gates of the MOSFETs used in the output stage of the speaker amplifier. This power supply is derived from the PVDD supply via an integrated linear regulator. A GVDD pin is provided for the attachment of decoupling capacitor for the gate drive voltage regulator. It is important to note that the linear regulator integrated in the device has only been designed to support the current requirements of the internal circuitry, and should not be used to power any additional external circuitry. Additional loading on this pin could cause the voltage to sag, negatively affecting the performance and operation of the device.

Another separate power supply is derived from the PVDD supply via an integrated linear regulator is AVDD. AVDD pin is provided for the attachment of decoupling capacitor for the TAS5825M internal circuitry. It is important to note that the linear regulator integrated in the device has only been designed to support the current requirements of the internal circuitry, and should not be used to power any additional external circuitry. Additional loading on this pin could cause the voltage to sag, negatively affecting the performance and operation of the device.

11 Layout

11.1 Layout Guidelines

11.1.1 General Guidelines for Audio Amplifiers

Audio amplifiers which incorporate switching output stages must have special attention paid to their layout and the layout of the supporting components used around them. The system level performance metrics, including thermal performance, electromagnetic compliance (EMC), device reliability, and audio performance are all affected by the device and supporting component layout.

Ideally, the guidance provided in the applications section with regard to device and component selection can be followed by precise adherence to the layout guidance shown in the *Layout Example* section. These examples represent exemplary baseline balance of the engineering trade-offs involved with lying out the device. These designs can be modified slightly as needed to meet the needs of a given application. In some applications, for instance, solution size can be compromised to improve thermal performance through the use of additional contiguous copper neat the device. Conversely, EMI performance can be prioritized over thermal performance by routing on internal traces and incorporating a via picket-fence and additional filtering components. In all cases, it is recommended to start from the guidance shown in the *Layout Example* section and work with TI field application engineers or through the E2E community to modify it based upon the application specific goals.

11.1.2 Importance of PVDD Bypass Capacitor Placement on PVDD Network

Placing the bypassing and decoupling capacitors close to supply has long been understood in the industry. This applies to DVDD, AVDD, GVDD and PVDD. However, the capacitors on the PVDD net for the TAS5782M device deserve special attention.

The small bypass capacitors on the PVDD lines of the DUT must be placed as close to the PVDD pins as possible. Not only dose placing these device far away from the pins increase the electromagnetic interference in the system, but doing so can also negatively affect the reliability of the device. Placement of these components too far from the TAS5782M device can cause ringing on the output pins that can cause the voltage on the output pin to exceed the maximum allowable ratings shown in the *Absolute Maximum Ratings* table, damaging the deice . For that reason, the capacitors on the PVDD net must be no further away from their associated PVDD pins than what is shown in the example layouts in the *Layout Example* section.

11.1.3 Optimizing Thermal Performance

Follow the layout example shown in the Figure 72 to achieve the best balance of solution size, thermal, audio, and electromagnetic performance. In some cases, deviation from this guidance can be required due to design constraints which cannot be avoided. In these instances, the system designer should ensure that the heat can get out of the device and into the ambient air surrounding the device. Fortunately, the heat created in the device naturally travels away from the device and into the lower temperature structures around the device.

11.1.3.1 Device, Copper, and Component Layout

Primarily, the goal of the PCB design is to minimize the thermal impedance in the path to those cooler structures. These tips should be followed to achieve that goal:

- Avoid placing other heat producing components or structures near the amplifier (including above or below in the end equipment).
- If possible, use a higher layer count PCB to provide more heat sinking capability for the TAS5825M device and to prevent traces and copper signal and power planes from breaking up the contiguous copper on the top and bottom layer.
- Place the TAS5825M device away from the edge of the PCB when possible to ensure that the heat can travel away from the device on all four sides.
- Avoid cutting off the flow of heat from the TAS5825M device to the surrounding areas with traces or via strings. Instead, route traces perpendicular to the device and line up vias in columns which are perpendicular to the device.
- Unless the area between two pads of a passive component is large enough to allow copper to flow in between the two pads, orient it so that the narrow end of the passive component is facing the TAS5782M device.
- Because the ground pins are the best conductors of heat in the package, maintain a contiguous ground plane

ADVANCE INFORMATION

Layout Guidelines (continued)

from the ground pins to the PCB area surrounding the device for as many of the ground pins as possible.

11.1.3.2 Stencil Pattern

The recommended drawings for the TAS5825M device PCB foot print and associated stencil pattern are shown at the end of this document in the package addendum. Additionally, baseline recommendations for the via arrangement under and around the device are given as a starting point for the PCB design. This guidance is provided to suit the majority of manufacturing capabilities in the industry and prioritizes manufacturability over all other performance criteria. In elevated ambient temperature or under high-power dissipation use-cases, this guidance may be too conservative and advanced PCB design techniques may be used to improve thermal performance of the system.

NOTE

The customer must verify that deviation from the guidance shown in the package addendum, including the deviation explained in this section, meets the customer's quality, reliability, and manufacturability goals.

11.1.3.2.1 PCB footprint and Via Arrangement

The PCB footprint (also known as a symbol or land pattern) communicates to the PCB fabrication vendor the shape and position of the copper patterns to which the TAS5825M device will be soldered. This footprint can be followed directly from the guidance in the package addendum at the end of this data sheet. It is important to make sure that the thermal pad, which connects electrically and thermally to the PowerPAD™ of the TAS5825M device, be made no smaller than what is specified in the package addendum. This ensures that the TAS5825M device has the largest interface possible to move heat from the device to the board.

The via pattern shown in the package addendum provides an improved interface to carry the heat from the device through to the layers of the PCB, because small diameter plated vias (with minimally-sized annular rings) present a low thermal-impedance path from the device into the PCB. Once into the PCB, the heat travels away from the device and into the surrounding structures and air. By increasing the number of vias, as shown in the *Layout Example* section, this interface can benefit from improved thermal performance.

NOTE

Vias can obstruct heat flow if they are not constructed properly.

More notes on the construction and placement of vias are as follows:

- Remove thermal reliefs on thermal vias, because they impede the flow of heat through the via.
- Vias filled with thermally conductive material are best, but a simple plated via can be used to avoid the additional cost of filled vias.
- The diameter of the drull must be 8 mm or less. Also, the distance between the via barrel and the surrounding planes should be minimized to help heat flow from the via into the surrounding copper material. In all cases, minimum spacing should be determined by the voltages present on the planes surrounding the via and minimized wherever possible.
- Vias should be arranged in columns, which extend in a line radially from the heat source to the surrounding area. This arrangement is shown in the *Layout Example* section.
- Ensure that vias do not cut off power current flow from the power supply through the planes on internal layers. If needed, remove some vias that are farthest from the TAS5825M device to open up the current path to and from the device.

11.1.3.2.2 Solder Stencil

During the PCB assembly process, a piece of metal called a stencil on top of the PCB and deposits solder paste on the PCB wherever there is an opening (called an aperture) in the stencil. The stencil determines the quantity and the location of solder paste that is applied to the PCB in the electronic manufacturing process. In most cases, the aperture for each of the component pads is almost the same size as the pad itself. However, the thermal pad on the PCB is large and depositing a large, single deposition of solder paste would lead to

Layout Guidelines (continued)

manufacturing issues. Instead, the solder is applied to the board in multiple apertures, to allow the solder paste to outgas during the assembly process and reduce the risk of solder bridging under the device. This structure is called an aperture array, and is shown in the *Layout Example* section. It is important that the total area of the aperture array (the area of all of the small apertures combined) covers between 70% and 80% of the area of the thermal pad itself.

11.2 Layout Example

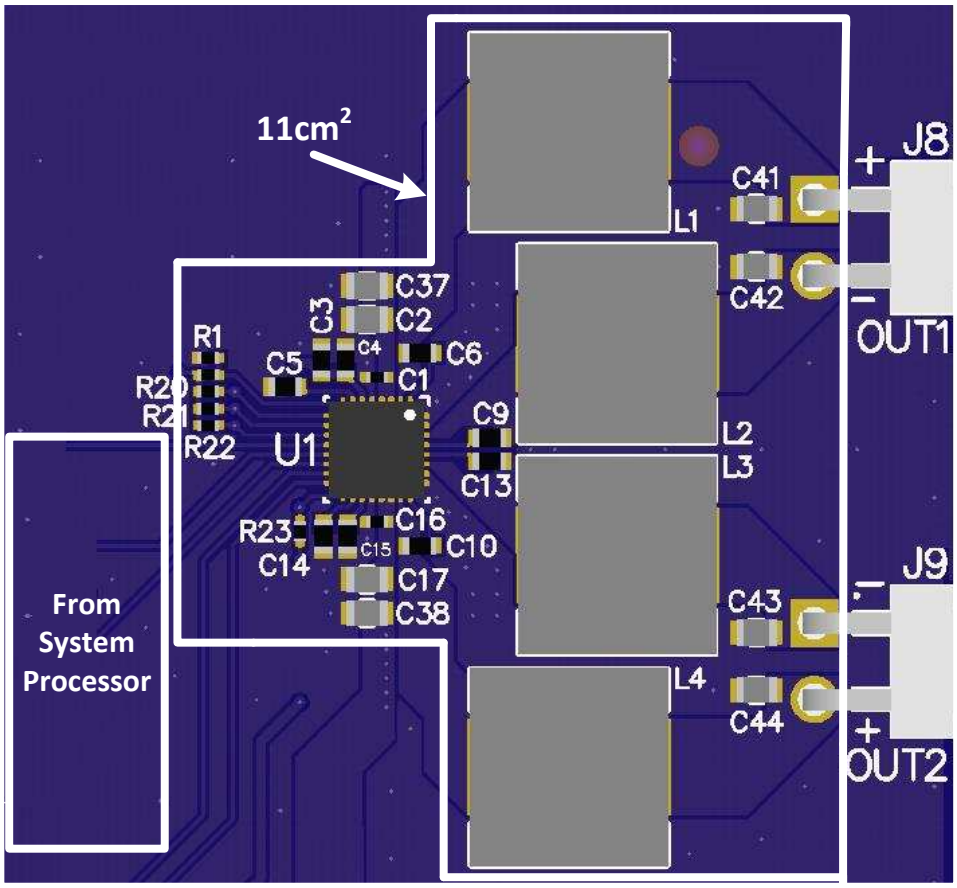

Figure 72. 2.0 (Stereo BTL) 3-D View

ADVANCE INFORMATION

Layout Example (continued)

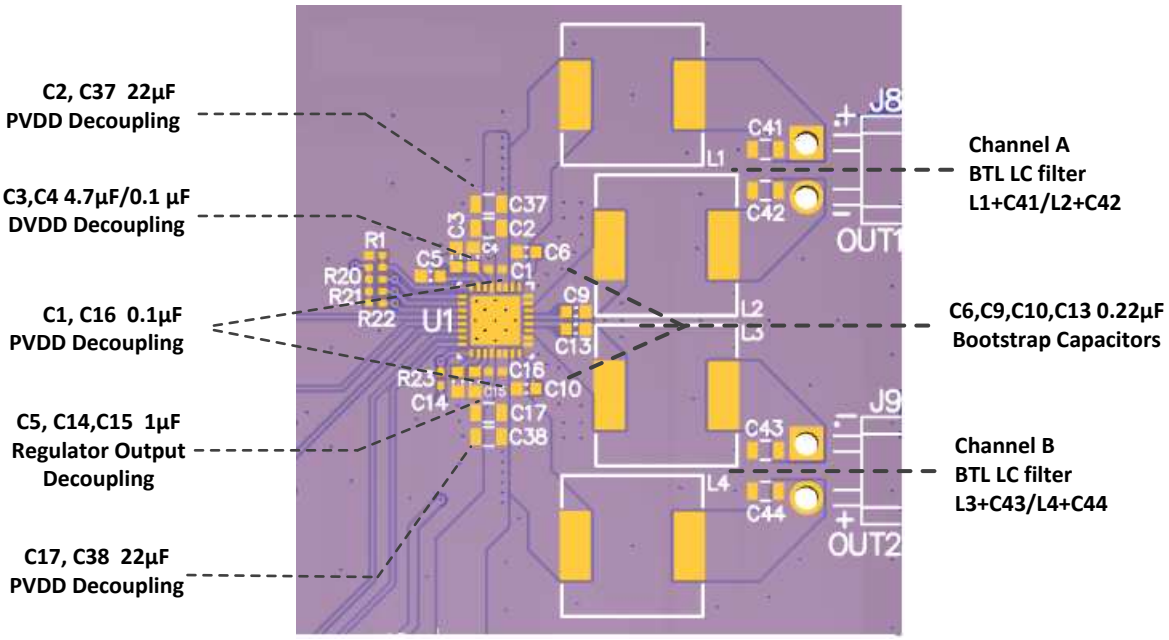

Figure 73. 2.0 (Stereo BTL) Top Copper View

ADVANCE INFORMATION

12 Device and Documentation Support

12.1 Device Support

12.1.1 Device Nomenclature

The glossary listed in the *Glossary* section is a general glossary with commonly used acronyms and words which are defined in accordance with a broad TI initiative to comply with industry standards such as JEDEC, IPC, IEEE, and others. The glossary provided in this section defines words, phrases, and acronyms that are unique to this product and documentation, collateral, or support tools and software used with this product. For any additional questions regarding definitions and terminology, please see the e2e Audio Amplfier Forum.

Bridge tied load (BTL) is an output configuration in which one terminal of the speaker is connected to one half-bridge and the other terminal is connected to another half-bridge.

DUT refers to a *device under test* to differentiate one device from another.

Closed-loop architecture describes a topology in which the amplifier monitors the output terminals, comparing the output signal to the input signal and attempts to correct for non-linearities in the output.

Dynamic controls are those which are changed during normal use by either the system or the end-user.

GPIO is a general purpose input/output pin. It is a highly configurable, bi-directional digital pin which can perform many functions as required by the system.

Host processor (also known as System Processor, Scalar, Host, or System Controller) refers to device which serves as a central system controller, providing control information to devices connected to it as well as gathering audio source data from devices upstream from it and distributing it to other devices. This device often configures the controls of the audio processing devices (like the) in the audio path in order to optimize the audio output of a loudspeaker based on frequency response, time alignment, target sound pressure level, safe operating area of the system, and user preference.

HybridFlow uses components which are built in RAM and components which are built in ROM to make a configurable device that is easier to use than a fully-programmable device while remaining flexible enough to be used in several applications

Maximum continuous output power refers to the maximum output power that the amplifier can continuously deliver without shutting down when operated in a 25°C ambient temperature. Testing is performed for the period of time required that their temperatures reach thermal equilibrium and are no longer increasing

Parallel bridge tied load (PBTL) is an output configuration in which one terminal of the speaker is connected to two half-bridges which have been placed in parallel and the other terminal is connected to another pair of half bridges placed in parallel

$\mathbf{r_{DS(on)}}$ is a measure of the on-resistance of the MOSFETs used in the output stage of the amplifier.

Static controls/Static configurations are controls which do not change while the system is in normal use.

Vias are copper-plated through-hole in a PCB.

12.1.2 Development Support

For RDGUI software, please consult your local field support engineer.

12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

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12.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.4 Trademarks

PowerPAD, E2E are trademarks of Texas Instruments.

12.5 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.6 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

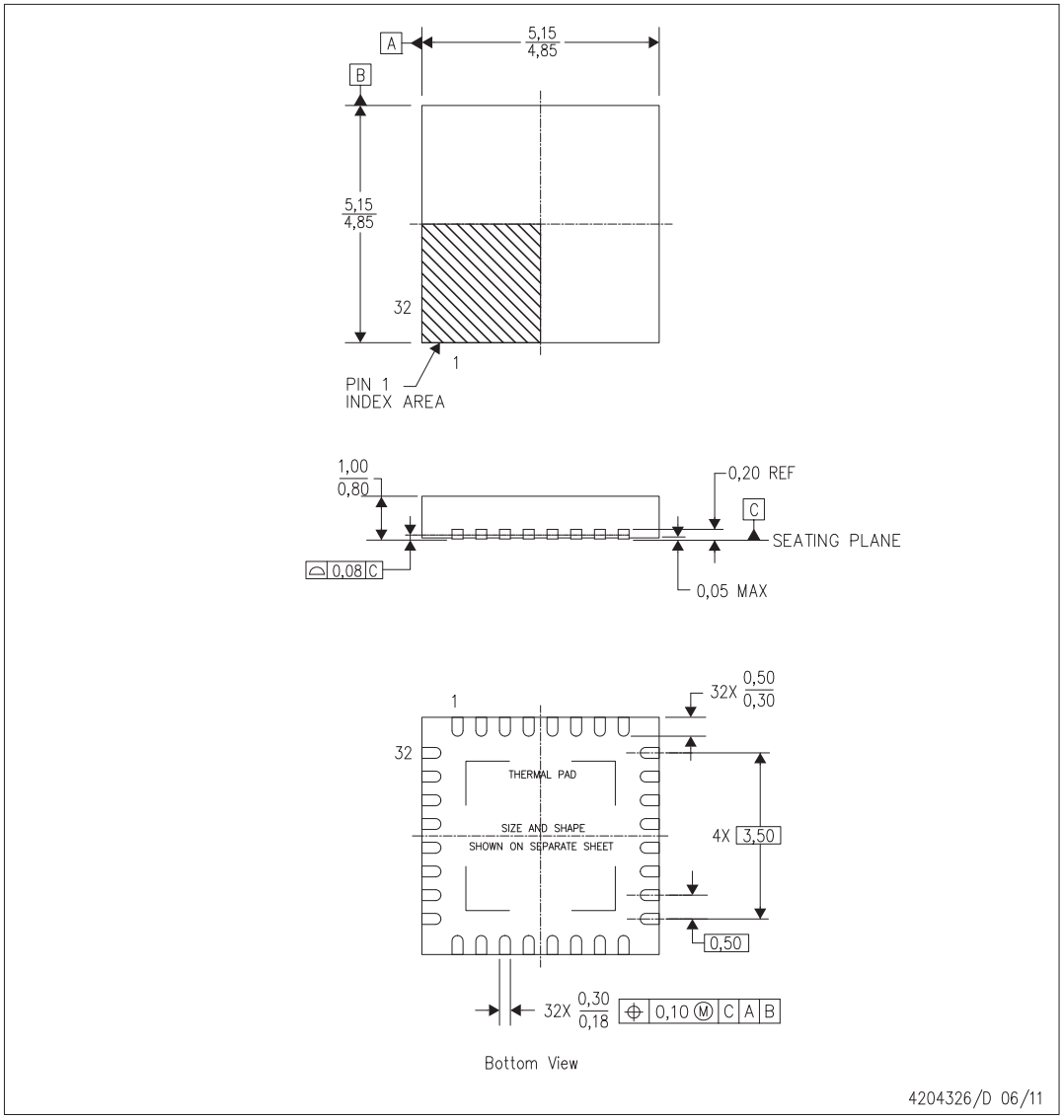
13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

ADVANCE INFORMATION

MECHANICAL DATA

RHB (S–PVQFN–N32) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No–Lead) Package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Falls within JEDEC MO–220.

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THERMAL PAD MECHANICAL DATA

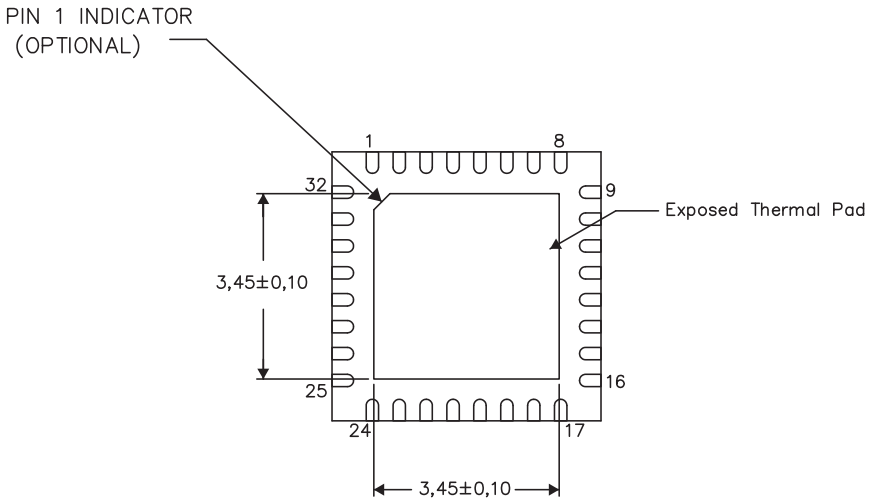
RHB (S–PVQFN–N32) PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

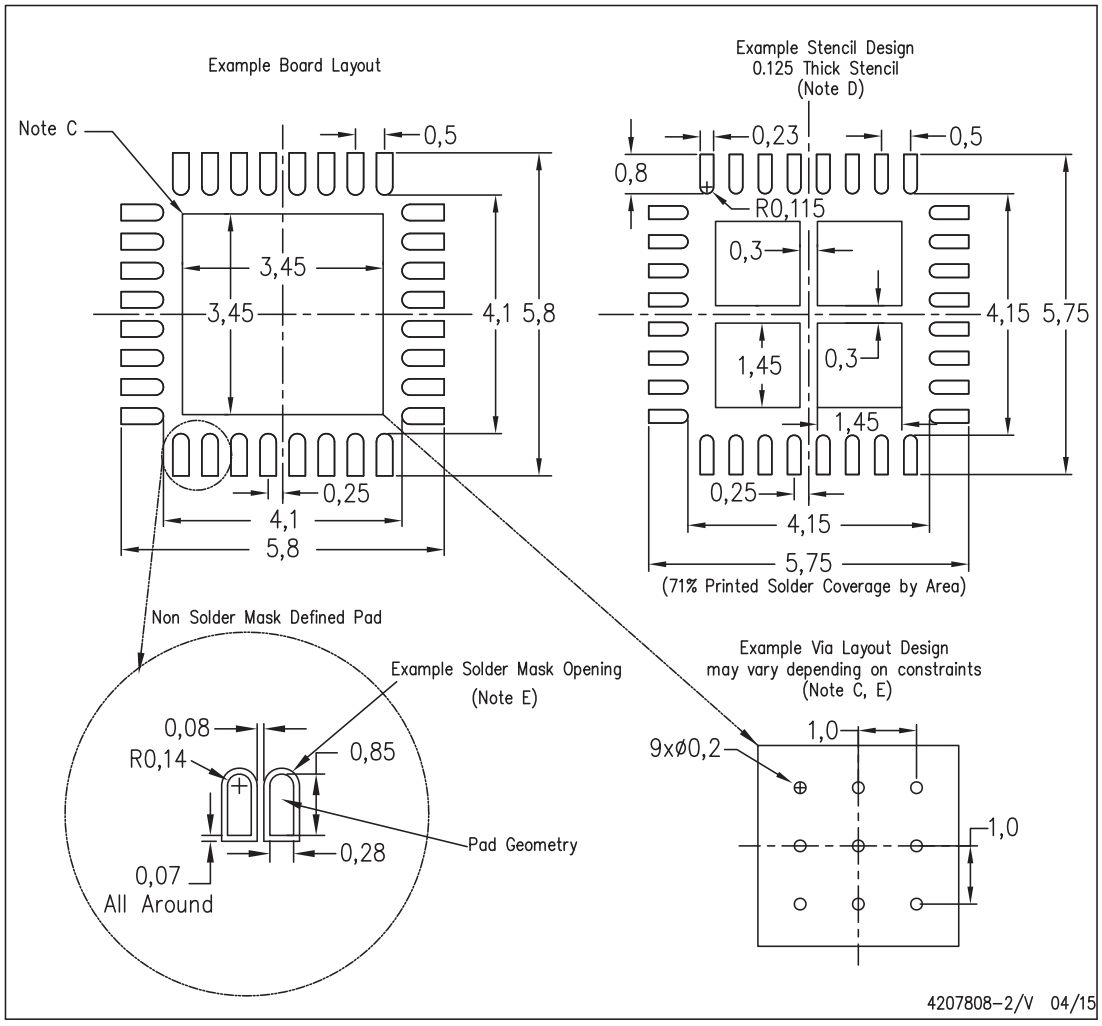
Exposed Thermal Pad Dimensions

4206356–2/AC 05/15

NOTE: A. All linear dimensions are in millimeters

LAND PATTERN DATA

RHB (S–PVQFN–N32) PLASTIC QUAD FLATPACK NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat–Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
E. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for any larger diameter vias placed in the thermal pad.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
PTAS5825MRHBR	ACTIVE	VQFN	RHB	32	3000	TBD	Call TI	Call TI	-25 to 85		Samples
TAS5825MRHBR	PREVIEW	VQFN	RHB	32	3000	TBD	Call TI	Call TI	-25 to 85		
TAS5825MRHBT	PREVIEW	VQFN	RHB	32	250	TBD	Call TI	Call TI	-25 to 85		

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
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Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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